

KEITHLEY

Model 7152 Low Current Matrix Card Instruction Manual

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Model 7152 Low Current Matrix Card Instruction Manual

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Test Instrumentation Group
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Cleveland, Ohio, U.S.A.
February 1989, First Printing
Document Number: 7152-901-01 Rev. A

SAFETY PRECAUTIONS

The following safety precautions should be observed before using the Model 7152 and the associated instruments.

This matrix card is intended for use by qualified personnel who recognize shock hazards and are familiar with the safety precautions required to avoid possible injury. Read over this manual carefully before using the card.

ALWAYS remove power from the entire system (mainframe, test instruments, DUT, etc.) and discharge any capacitors before doing any of the following:

1. Installing or removing the matrix card from the mainframe.
2. Connecting or disconnecting cables from the matrix card.

Exercise extreme caution when a shock hazard is present at the test fixture. User-supplied lethal voltages may be present on the fixture or the connector jack. The American National Standards Institute (ANSI) states that a shock hazard exists when voltage levels greater than 30V RMS or 42.4V peak are present. A good safety practice is to expect that hazardous voltage is present in any unknown circuit before measuring.

Do not exceed 200V between any two pins or between any pin and chassis ground.

Inspect the connecting cables and test leads for possible wear, cracks, or breaks before each use.

For maximum safety, do not touch the test fixture, test cables or any instruments while power is applied to the circuit under test.

Do not touch any object which could provide a current path to the common side of the circuit under test or power line (earth) ground.

Do not exceed the maximum signal levels of the test fixture, as defined in the specifications and operation section of this manual.

Do not connect the matrix card directly to unlimited power circuits. This product is intended to be used with impedance limited sources. NEVER connect the matrix card directly to ac mains.

When connecting sources, install protective devices to limit fault current and voltage to the card.

The chassis connections must only be used as shield connections for measuring circuits; NOT as safety earth ground connections.

The outer shields (including the triax connector shells) of the Model 7152-TRX-10 are not connected to chassis of the Model 7152. NEVER apply 30V or more to these shields.

Instrumentation and accessories should not be connected to humans.

SPECIFICATIONS

MATRIX CONFIGURATION: 4 rows by 5 columns.

CROSSPOINT CONFIGURATION: 2-pole Form A (SIGNAL and GUARD)

CONNECTOR TYPE: Subminiature coax, M-Series receptacle.

RELAY DRIVE CURRENT: 20mA (per crosspoint).

PEAK CONTACT RATING:

200V, 1A carry/0.5A switched.

10VA (resistive load).

PEAK VOLTAGE:

Common Mode: 200V (signal or guard to chassis).

Path-Path: 200V (signal or guard to signal or guard).

CONTACT LIFE:

10^8 closures (cold switching),

10^5 closures (at maximum signal level).

PATH RESISTANCE: $<2\Omega$ per contact to rated life.

ACTUATION TIME: <2 msec. exclusive of mainframe.

ISOLATION:

Path: $>10^{13}\Omega$ and <1 pF.

Differential: $>10^{11}\Omega$ and <100 pF.

Common Mode: $>10^9\Omega$ and <300 pF.

CROSSTALK: <-50 dB at 1 MHz, 50 Ω load.

INSERTION LOSS: 0.1 dB typical (1MHz, 50 Ω source, 50 Ω load).

3dB BANDWIDTH: 60MHz typical (50 Ω load).

OFFSET CURRENT: <1 pA (10fA typical).

CONTACT POTENTIAL: 20 μ V per contact typical.

ENVIRONMENT:

ISOLATION and OFFSET CURRENT Specifications: 23 $^{\circ}$ C, $<60\%$ R.H.

Operating: 0 $^{\circ}$ to 50 $^{\circ}$ C, up to 35 $^{\circ}$ C at 70% RH.

Storage: -25 $^{\circ}$ to 65 $^{\circ}$ C.

DIMENSIONS, WEIGHT: 32mm high \times 114mm wide \times 286mm long (1.25 in. \times 4.5 in. \times 11.25 in.). Net weight 0.60 kg (21.0 oz.).

ACCESSORIES SUPPLIED: Instruction manual, connector caps.

ACCESSORIES AVAILABLE:

Model 7074-CIT:

Model 7074-HCT:

Model 7152-MTC-2:

Model 7152-MTC-10:

Model 7152-TRX-10:

Model 7152-KIT:

Model 7152-MTR:

Model 7152-HCT:

Extraction Tool for 7152-KIT, 7152-MTR

Hand Crimp Tool for 7152-KIT, 7152-MTR shield contacts

Low Noise Matrix Expansion Cable, 0.6m (2 ft.)

Low Noise Matrix Expansion Cable, 3m (10 ft.)

Low Noise M-Series to Triax Cable, 3m (10 ft.)

6-Position M-Series Plug, with subminiature pins

6-Position M-Series Receptacle, with subminiature sockets

Hand Crimp Tool for 7152-KIT, 7152-MTR coaxial contacts

Specifications subject to change without notice.

HOW TO USE THIS MANUAL

Contains information on Model 7152 features, specifications, and accessories.

SECTION 1 **General Information**

Details installation of the Model 7152 Low Current Matrix Card within the Model 705 and 706 scanners, covers card connections, and also discusses matrix mainframe programming and measurement considerations.

SECTION 2 **Operation**

Gives three typical applications for the Model 7152, including semiconductor switching matrix, van der Pauw resistivity measurements, and semiconductor parameter analysis using the HP 4145B.

SECTION 3 **Applications**

Contains Matrix card cleaning and performance verification procedures for the matrix card.

SECTION 4 **Service Information**

Lists replacement parts, and also includes component layout and schematic drawing for the Model 7152

SECTION 5 **Replaceable Parts**

Provides a diagram of the Model 7152 with space provided for identifying connections to instrumentation, DUT, and other cards.

APPENDIX A **System Configuration** **Worksheet**

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SECTION 1

General Information

1.1 INTRODUCTION

This section contains general information about the Model 7152 Low Current Matrix Card and is arranged as follows:

1.2 Features

1.3 Warranty Information

1.4 Manual Addenda

1.5 Safety Symbols and Terms

1.6 Specifications

1.7 Unpacking and Inspection

1.8 Repacking for Shipment

1.9 Optional Accessories

1.2 FEATURES

Key features of the Model 7152 Low Current Matrix Card include:

- 4 × 5 (four row by five column) switching matrix.
- Low offset current for low-current measurements.
- Subminiature coax, multiple contact IN and OUT receptacles simplify matrix expansion.

1.3 WARRANTY INFORMATION


Warranty information is located on the inside front cover of this instruction manual. Should your Model 7152 require warranty service, contact the Keithley representative or authorized repair facility in your area for further information. When returning the matrix card for repair, be sure to fill out and include the service form at the back of this manual in order to provide the repair facility with the necessary information.


1.4 MANUAL ADDENDA

Any improvements or changes concerning the matrix card or manual will be explained in an addendum included with the the unit. Be sure to note these changes and incorporate them into the manual before using or servicing the unit.

1.5 SAFETY SYMBOLS AND TERMS

The following symbols and terms may be found on an instrument or used in this manual.

The  symbol on an instrument indicates that the user should refer to the operating instructions located in the instruction manual.

The  symbol on an instrument shows that 1kV or greater may be present on the terminal(s). Use standard safety precautions to avoid personal contact with these voltages.

The **WARNING** heading used in this manual explains dangers that might result in personal injury or death. Always read the associated information carefully before performing the indicated procedure.

The **CAUTION** heading used in this manual explains hazards that could damage the matrix card. Such damage may invalidate the warranty.

1.6 SPECIFICATIONS

Model 7152 specifications are located at the front of this manual. These specifications are exclusive of the mainframe specifications, which are located in their respective instruction manuals.

1.7 UNPACKING AND INSPECTION

1.7.1 Inspection for Damage

Upon receiving the Model 7152, carefully unpack it from its shipping carton and inspect the card for any obvious signs of physical damage. Report any such damage to the shipping agent immediately. Save the original packing carton for possible future reshipment.

1.7.2 Shipment Contents

The following items are included with every Model 7152 order:

- Model 7152 Low Current Matrix Card.
- Model 7152 Instruction Manual.
- Protection caps installed on card receptacles.
- Additional accessories as ordered.

1.7.3 Additional Instruction Manual

If an additional instruction manual is required, order the manual package, Keithley part number 7152-901-00. The manual package includes an instruction manual and any pertinent addenda.

1.8 REPACKING FOR SHIPMENT

Should it become necessary to return the Model 7152 for repair, carefully pack the unit in its original packing carton or the equivalent, and include the following information:

- Advise as to the warranty status of the matrix card.
- Write ATTENTION REPAIR DEPARTMENT on the shipping label.
- Fill out and include the service form located at the back of this manual.

1.9 OPTIONAL ACCESSORIES

The following accessories are available to make connections to the Model 7152.

Model 7152-MTC Cable — This is a low noise, mass terminated triax cable assembly. This cable is terminated with subminiature, multiple-contact plugs that will mate to the receptacles on the matrix card. This cable is used for matrix expansion, and, when cut in half, can be used for connections to external circuitry. The Model 7152-MTC-2 is two feet in length, while the 7152-MTC-10 is 10 feet in length.

Model 7152-TRX-10 — This 10-foot cable assembly is made up of five individual triax cables. One end of the cable assembly is terminated with a subminiature, multiple-contact plug that will mate to the matrix card receptacles. The other end of the cable assembly is terminated with five 3-slot male triax connectors.

Model 7152-KIT — This connection kit contains one subminiature coax, multiple-contact plug housing, and six contacts. This kit allows custom cables to be built that will mate to the matrix card receptacles. The Model 7152-HCT crimping tool is required to crimp the coax contacts. The Model 7074-HCT is required to crimp the chassis contact.

Model 7152-MTR — This connection kit contains one subminiature coax, multiple contact bulkhead receptacle housing, and six contacts. This is the same receptacle used on the matrix card and can be mounted on a user-supplied test fixture. The Model 7152-HCT crimping tool is required to crimp the coax contacts. The Model 7074-HCT is required to crimp the chassis contact.

Model 7152-HCT — This tool is used to crimp subminiature coax contacts. This tool is required for the Models 7152-KIT and 7152-MTR connection kits.

Model 7074-CIT — This extraction tool is used to remove subminiature contacts from plug and receptacle housings.

Model 7074-HCT — This tool is used to crimp the chassis contacts. This tool is required for the Model 7152-KIT and 7152-MTR connection kits.

SECTION 2

Operation

2.1 INTRODUCTION

This section contains information on aspects of matrix card operation and is arranged as follows:

2.2 Handling Precautions: Details precautions that should be observed when handling the matrix card to ensure that its performance is not degraded due to contamination.

2.3 Environmental Considerations: Outlines environmental aspects of using the Model 7152.

2.4 Equivalent Circuit: Provides the simplified matrix card circuit for the Model 7152.

2.5 Card Installation and Removal: Covers the basic procedures for installing and removing the matrix card from the Model 705 or 706 mainframe.

2.6 Connections: Discusses card connectors, cables and adapters, and typical connections to other instrumentation and DUT test fixtures.

2.7 Matrix Expansion: Covers the various matrix configurations that are possible by using multiple matrix cards.

2.8 Mainframe Control of Matrix Card: Covers the operating aspects specific to the Model 7152.

2.9 Measurement Considerations: Reviews a number of considerations when making low-level measurements.

2.2 HANDLING PRECAUTIONS

To maintain high impedance isolation, care should be taken when handling the matrix card to avoid contamination from such foreign materi-

als as body oils. Such contamination can substantially lower leakage resistances, degrading performance.

To avoid possible contamination, always grasp the card by the side edges. Do not touch the edge connectors of the card and do not touch board surfaces or components. When not installed in a mainframe, keep the card in the bag and store in the original packing carton.

Dirt build-up over a period of time is another possible source of contamination. To avoid this problem, operate the mainframe and matrix card only in a clean environment.

If the card should become contaminated, it should be thoroughly cleaned as explained in paragraph 4.2.

2.3 ENVIRONMENTAL CONSIDERATIONS

For rated performance, the card should be operated within the temperature and humidity limits given in the specifications at the front of this manual. Note that current offset and path isolation values are specified within a lower range of limits than the general operating environment.

2.4 EQUIVALENT CIRCUIT

A simplified schematic of the Model 7152 4×5 matrix card is shown in Figure 2-1. Each of the 20 crosspoints is made up of a two-pole switch. In this simple configuration any row can be connected to any column by closing the appropriate crosspoint. Mainframe control of matrix crosspoints is covered in paragraph 2.8.

NOTE

A diagram of the Model 7152 is provided in Appendix A. This system configuration worksheet makes it convenient to plan a matrix system. Additional space is provided for drawings and notes.

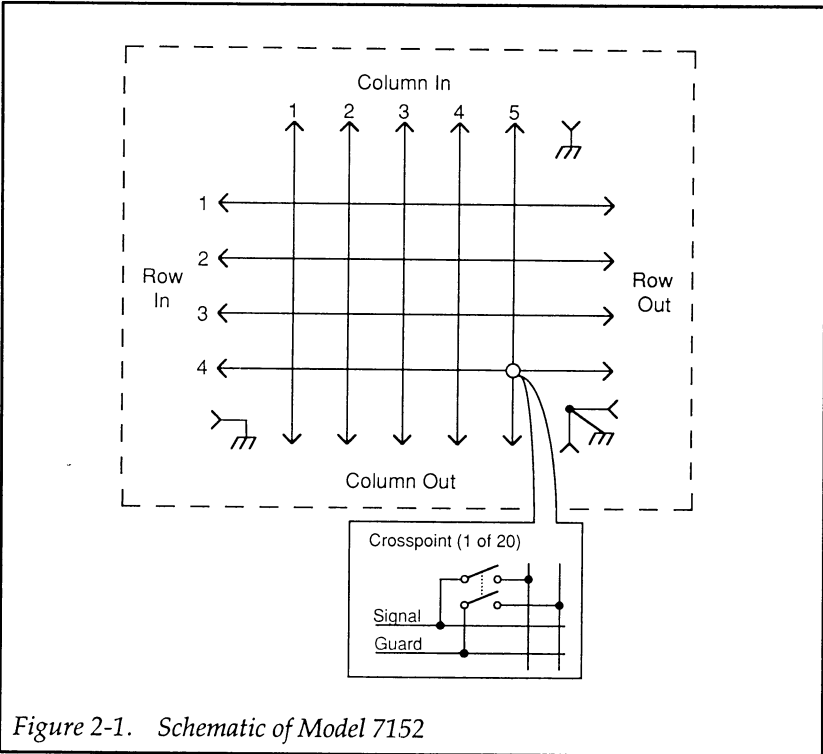


Figure 2-1. Schematic of Model 7152

2.5 CARD INSTALLATION AND REMOVAL

The following procedures explain how to install and remove the Model 7152 matrix card from the Models 705 and 706 mainframes.

WARNING

To prevent electrical shock which could result in injury or death, turn off the mainframe power and disconnect the line cord before installing or removing matrix cards. If there are cables connected to the card, also remove power from those circuits before proceeding.

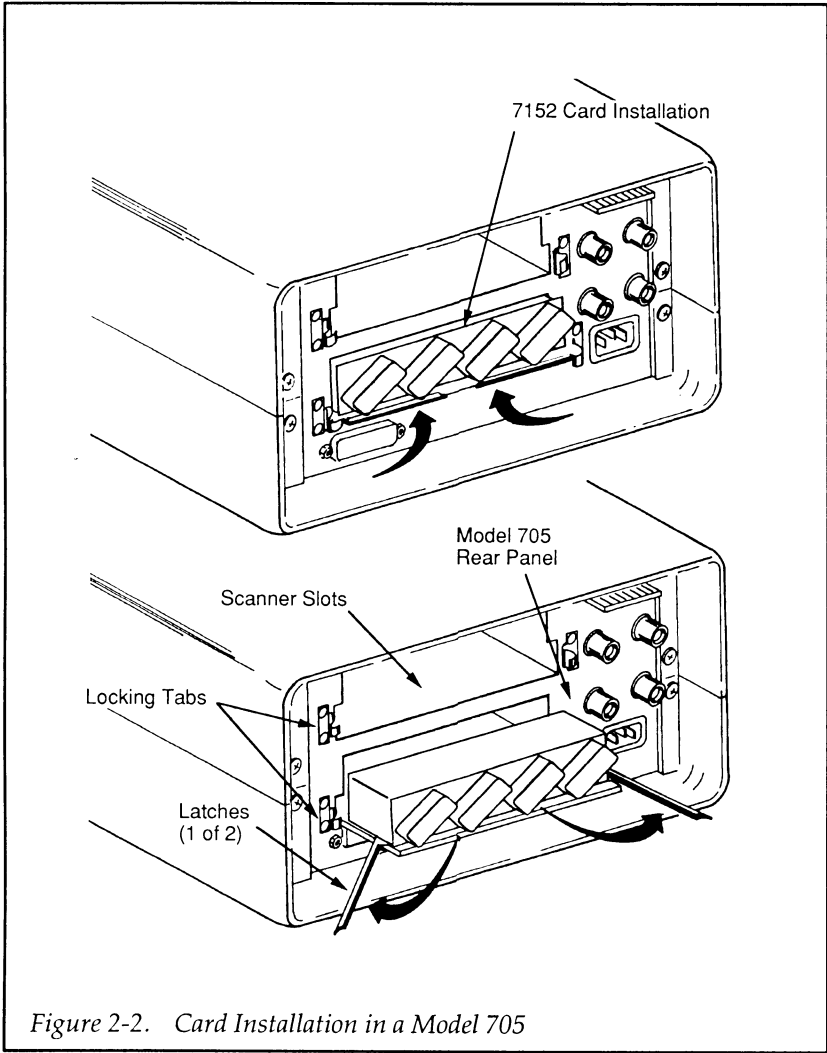
CAUTION

Contamination will degrade the performance of the matrix card. To avoid contamination, always grasp the card by the side edges. Do not touch the board surfaces or components.

2.5.1 Matrix Card Installation

Perform the following procedure to install the Model 7152 matrix card in either the Model 705 or Model 706 mainframe. Refer to Figure 2-2 to install the card in the Model 705 and refer to Figure 2-3 to install the card in the Model 706.

1. Slide the card into the desired slot as shown in the appropriate illustration. Make sure the card edges of the bottom shield board are properly aligned with the grooves in the receptacle.
2. Once the card is almost all the way in the slot, and you encounter resistance, push firmly on the edge of the card to seat it in the edge connector.
3. Once the card is fully seated, lock the card in place by placing the latches in the locked position.



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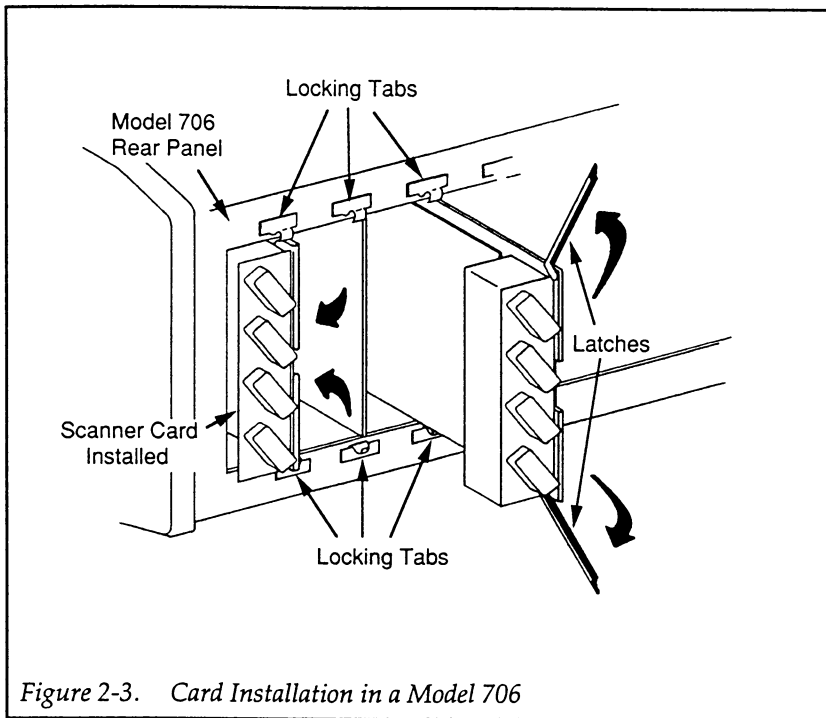


Figure 2-3. Card Installation in a Model 706

2.5.2 Matrix Card Removal

To remove the matrix card, first unlock it by pulling the latches outward, then grasp the end of the card at the edges, and pull the card out of the mainframe.

2.6 INSTRUMENT AND DUT CONNECTIONS

The information in the following paragraph explains how to connect the matrix card to external test circuitry (instruments and DUT). For information on making matrix expansion connections, see paragraph 2.7.1.

CAUTION

Do not connect the matrix card to unlimited power circuits. This product is intended for use with impedance limited sources. Do not connect directly to ac mains.

When connecting an impedance limited source, install appropriate protection (such as a fuse or a clamping circuit) to limit potentially damaging fault currents to the matrix card.

CAUTION

Contamination will degrade the performance of the matrix card. To avoid contamination, always grasp the card by the side edges. Do not touch the board surfaces or components.

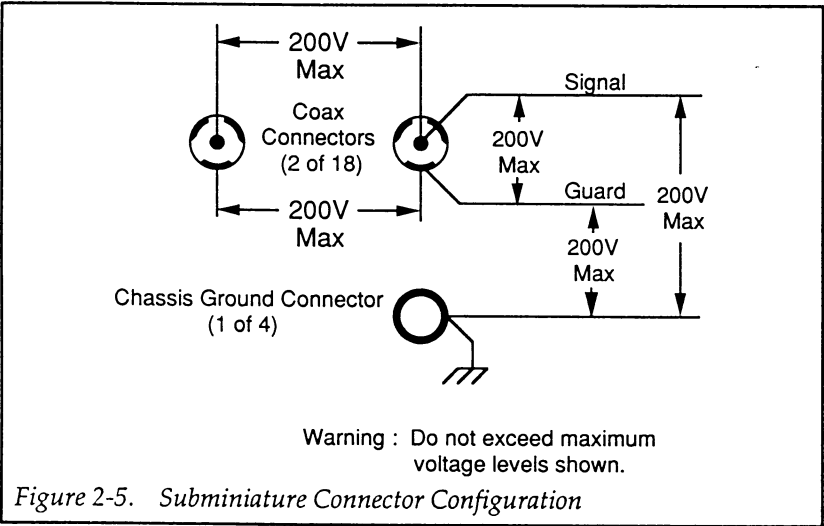
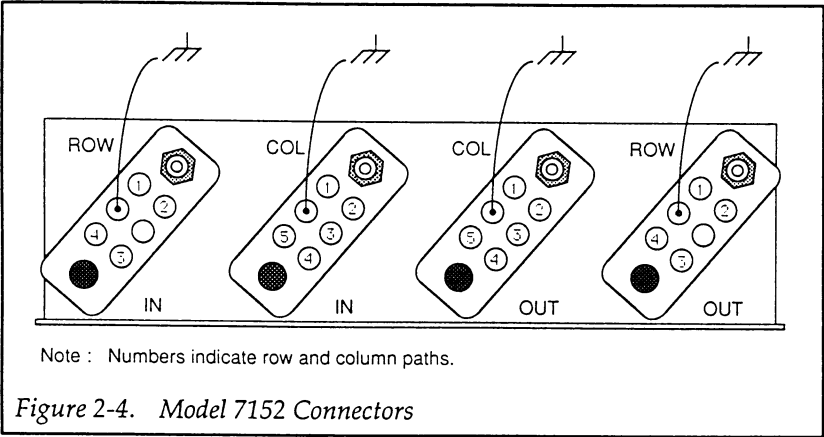
Card connectors, recommended cables and adapters, and typical connections to instruments and DUT are discussed in the following paragraphs.

2.6.1 Card Connectors

The card connectors are shown in Figure 2-4. There are four subminiature coaxial, multiple contact receptacles. Two of the receptacles are used for ROW connections (IN and OUT) and the other two are used for

SECTION 2
Operation

COLUMN connections (IN and OUT). ROW and COLUMN number designations are included in the illustration. Notice that one contact of each receptacle is reserved for chassis ground. For each coaxial connector, as shown in Figure 2-5, the center conductor is SIGNAL, and the outer shell is GUARD.



WARNING

Do not exceed 200V between SIGNAL and GUARD, or between SIGNAL and chassis ground, or between GUARD and chassis ground or between paths (see Figure 2-5). Also, do not exceed 1A carry/500mA switched, 10VA peak (resistive load).

As shipped, the receptacles have protective caps installed on them. These caps are connected to chassis ground to help prevent electrical noise from being induced into the card. These caps also help keep the connectors clean. Only remove the caps from the receptacles that are going to be used.

Dual receptacles (IN and OUT) for rows and columns are provided to make matrix expansion simple (see paragraph 2.7). Thus, one row receptacle (IN or OUT) should be used for instrumentation and/or DUT, and the other row receptacle should be reserved for matrix expansion. The same applies to columns. Use one column receptacle (IN or OUT) for DUT and/or instrumentation, and use the other for expansion.

CAUTION

To prevent damage to the matrix card and other equipment, do not connect equipment such that they short out on the same row or column. Remember, ROWs IN are connected to ROWs OUT, and COLs IN are connected to COLs OUT (see Figure 2-1).

2.6.2 Recommended Cables and Adapters

Table 2-1 summarizes the cables and adapters recommended for use with the Model 7152.

NOTE

Equivalent user-supplied items may be substituted as long as they are of sufficient quality (low offset current, high leakage resistance). Using substandard cables and adapters may degrade the integrity of the measurements made using the

Table 2-1. Recommended Cables and Adapters

Item	Manufacturer	Model or Part No.	Description	Applications
1	Keithley	7152-MTC-2, 7152-MTC-10	Matrix expansion cables	Matrix expansion, input/output connections
2	Keithley	7152-TRX-10	Matrix to triax cable	7152 input/output connections
3	Keithley	6172	2-slot male to 3-lug female triax adapter	Connect 3-slot triax cable to 2-lug triax connector
4	Pomona	5278	3-lug female to female triax adapter	Connect male triax cable to male triax cable
5	Keithley	7078-TRX-10	3-slot triax cable	Connect to 7152-TRX-10 cable through 5278 adapter
6	Keithley	BG-10-2	Banana plug, red	Banana plug cable (see paragraph 2.6.3)
7	Keithley	6167*	Guarded adapter	220 Current Source Connections

*6167 requires modification by disconnecting input LO internally.

matrix card. See paragraph 2.9 for a discussion of measurement considerations.

The following discussion provides additional information about the recommended Keithley cables; the Model 7152-MTC cable and the Model 7152-TRX-10 cable.

Model 7152-MTC Low Noise Matrix Expansion Cables

The Model 7152-MTC-2 is a 2 ft. (0.6 m) cable assembly that is terminated with subminiature coaxial, multiple contact plugs. The Model 7152-MTC-10 is the same as the Model 7152-MTC-2 except that it is 10 ft. (3m) in length. The plugs on these cables will mate to the ROW and COL receptacles on the matrix card. They are used for matrix expansion (see paragraph 2.7) or can be modified for connections to DUT and instrumentation. Figure 2-6 provides the pin identification for the Model 7152-MTC plug.

The five individual cables of the cable assembly are triaxial. Chassis ground is routed from pin D of the two plugs through the outer shields of the five triax cables. The physical connections for chassis ground are made at the two plugs.

Model 7152-TRX-10 Low Noise Matrix to Triax Cable

The Model 7152-TRX-10 is a 10 ft. (3m) cable assembly that is terminated with a subminiature coaxial, multiple contact plug at one end, and five 3-slot male triax connectors at the other end. The plug end of the cable will mate to the ROW and COLUMN receptacles of the matrix card. This is the same plug used on the Model 7152-MTC cable. The triax connectors will mate to standard 3-lug female triax connectors. Each triax cable is labeled and corresponds to a ROW or COLUMN as follows:

Triax #1 = Row 1 or Column 1
Triax #2 = Row 2 or Column 2
Triax #3 = Column 3
Triax #4 = Row 3 or Column 4
Triax #5 = Row 4 or Column 5

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Operation

On each triax connector, as shown in Figure 2-7, the center conductor is SIGNAL, the inner shield is GUARD, and the connector shell is connected to the outer shield of the cable. Note that this outer shield is connected to chassis of the Model 7152.

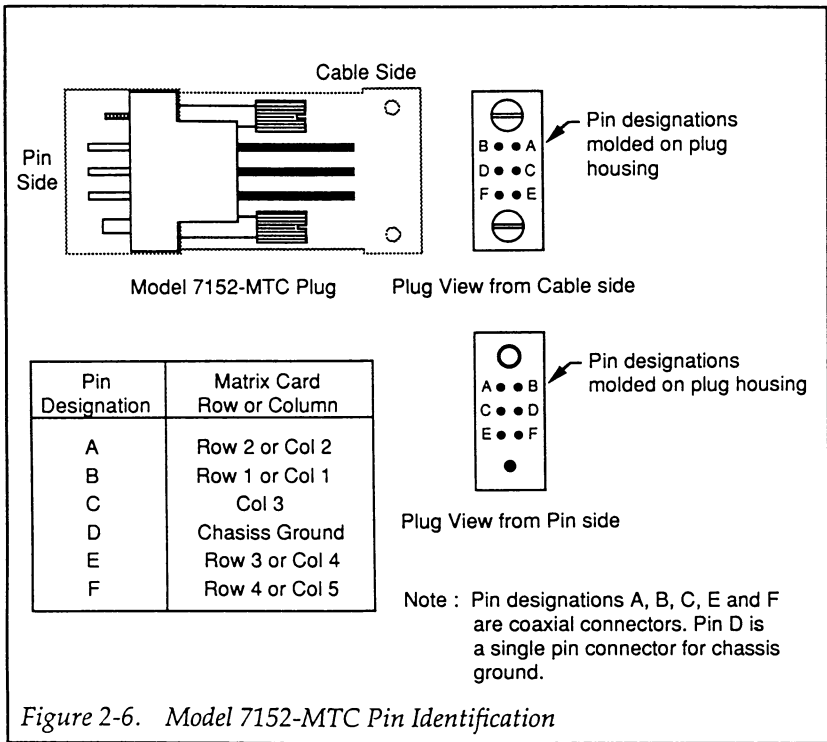


Figure 2-6. Model 7152-MTC Pin Identification

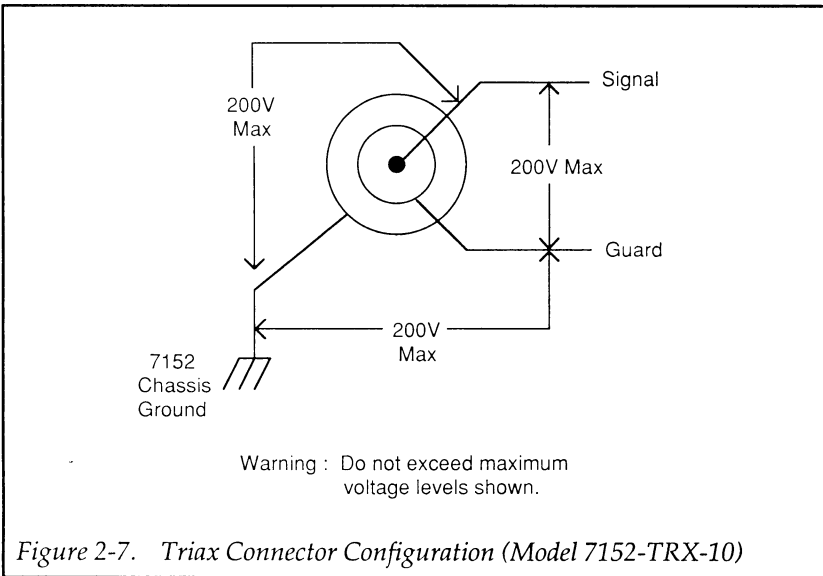


Figure 2-7. Triax Connector Configuration (Model 7152-TRX-10)

2.6.3 Special Cabling Requirements

For instruments that use banana jacks, cables that are terminated with single banana plugs will be required. Preparation of these cables are explained as follows.

Matrix to Banana Cable

For applications where only banana plugs are needed, the Model 7152-MTC-10 cable can be cut in half resulting in two five-foot matrix cable assemblies that are unterminated at one end. Single banana plugs can then be attached to the appropriate cables. The procedure to connect a single banana plug to the triax cable is explained below (see Attaching Banana Plug To Triax Cable) and in Figure 2-8.

Triax to Banana Cables

For applications where a combination of triax connectors and single banana plugs are needed, it is recommended that separate triax to banana

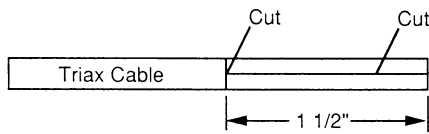
cables be built. With the use of a female to female triax adapter, the triax/banana cable can then be mated to the appropriate male triax connector of the Model 7152-TRX-10 Matrix to Triax cable.

To build triax to banana cables, it is recommended that you start out with a triax cable that is terminated with 3-lug male triax connectors on both ends, such as the Keithley Model 7078-TRX-10 (Item 5 in Table 2-1). Cutting this triax cable in half will provide two five-foot triax cables that are unterminated on one end. A single banana plug can then be attached to each of the two cables. The procedure to connect a single banana plug to the triax cable is explained below (see Attaching Banana Plug To Triax Cable) and in Figure 2-8. A female to female triax adapter that will allow the triax/banana cable to mate to the triax connectors of the Model 7152-TRX-10 is listed in Table 2-1 (Item 4).

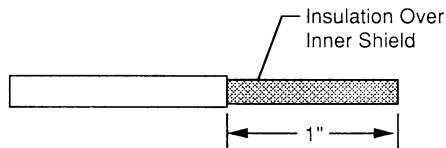
Attaching Banana Plug To Triax Cable

The following procedure, along with Figure 2-8, explain how to connect a single banana plug (Item 6 in Table 2-1) to a triax cable.

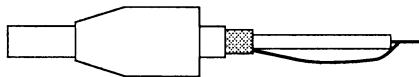
1. Using an X-Acto® knife, cut and strip back the outer insulation about 1-1/2 inches.
2. Remove the outer insulation, then cut away the outer shield back as far as the insulation is stripped.
3. Carefully strip away the insulation over the inner shield one inch, then cut the inner shield off even with the stripped insulation.
4. Strip the inner conductor 1/2 inch, then twist the strands together.
5. Unscrew the cover from a banana plug, then slide the cover over the center conductor of the triax cable.
6. Insert the stripped center conductor through the hole in the body of the banana plug, then wrap the wire around the plug body.
7. Screw on the plastic cover, and make certain the wire is secure by gently pulling on the plug.



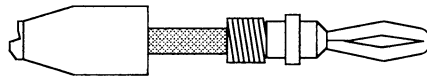
- (A) Cut off insulation with knife.
Cut off outer shield.



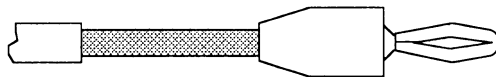
- (B) Strip insulation off Inner shield.



- (C) Twist inner shield then strip Inner conductor.
Twist inner shield and center conductor together,
slip on plastic cover.



- (D) Insert wires into hole and wrap around body.



- (E) Screw on plastic cover.

Figure 2-8. Attaching Banana Plug to Triax Cable

2.6.4 General Instrument Connections

The following paragraphs discuss connecting the Model 7152 to various general classes of instrumentation such as DMMs, electrometers, sources, and source/measure units. Because these configurations are generic in nature, some modification of the connecting schemes may be necessary for your particular instrumentation. Also, special cables or adapters may be necessary.

WARNING

Do not use coaxial cables and adapters because hazardous voltage from guard sources may be present on the cable shields.

Figure 2-9 shows the general instrument connections for the discussions below. Note that DUT guarding or shielding are not indicated here; see Figure 2-23 and Figure 2-26 for shielding and guarding information. As shown, all figures assume instruments are connected to rows, and the DUT is connected to columns.

DMM Connections

General DMM connections are shown in Figure 2-9(A), (B), and (C). Floating connections are shown in (A), with LO and HI routed to two separate rows on the Model 7152. The common LO connections in (B) should be used only for non-critical applications because the performance (isolation) of the GUARD pathway is not as good as a SIGNAL pathway.

WARNING

Hazardous voltage from other guard sources may be present on LO or the DUT if other crosspoints are closed.

Four-wire DMM connections are shown in Figure 2-9(C). In this case, a total of four rows are required; one row for HI, one for LO, one for SENSE HI, and one for SENSE LO.

Electrometer Connections

Typical electrometer connections are shown in Figure 2-9(D) through (G). The unguarded volts connections in (D) show the HI signal path routed to one row, and the LO path goes to a another row. Both GUARD pathways are connected to electrometer LO. For guarded voltage (E), Model 7152 GUARD is connected to electrometer GUARD.

The connections for electrometer fast amps and resistance measurements are shown in Figure 2-9(F) and (G). These configurations are essentially the same as those discussed above. For the case of fast amps, both GUARD paths are connected to electrometer LO, while in the case of guarded resistance, one GUARD path is connected to electrometer GUARD, and the other GUARD path is connected to electrometer LO.

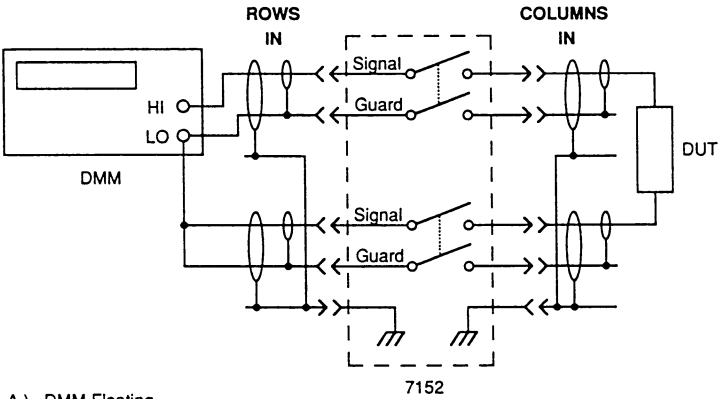
Source Connections

Voltage and current source connections are shown in Figure 2-9(H) through (J). The HI and LO paths of the voltage source (H) are routed through two rows, with both card GUARD pathways connected to voltage source LO. For the unguarded current source connections (I), card GUARD is again connected to source LO, with source HI and LO routed through two rows. In the case of the guarded current source in (J), card GUARD of the HI signal path is connected to source GUARD, and the other GUARD path is connected to source LO.

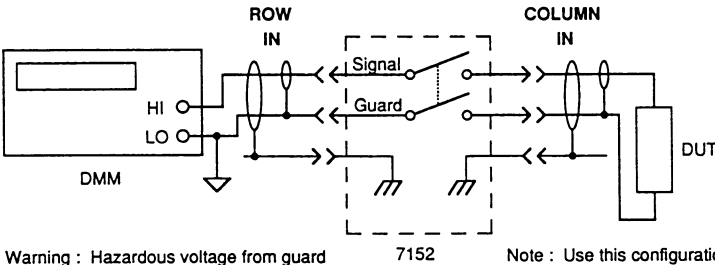
Source/Measure Unit Connections

Figure 2-9(K) shows typical connections for a source/measure unit (SMU). In this instance, a remote-sensing type of a SMU is shown, requiring a total of four signal pathways to the DUT. For critical measurements, both source and sense HI pathways would be guarded as shown, with two of the four card GUARD pathways connected to SMU GUARD terminals. As with other instrument connections, the LO card GUARD pathways are connected to SMU LO terminals.

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A.) DMM Floating

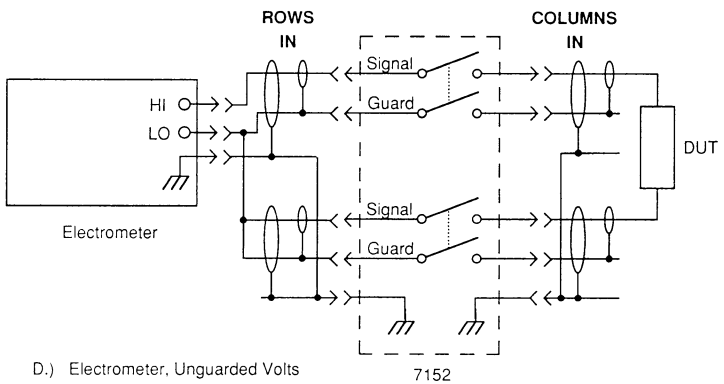
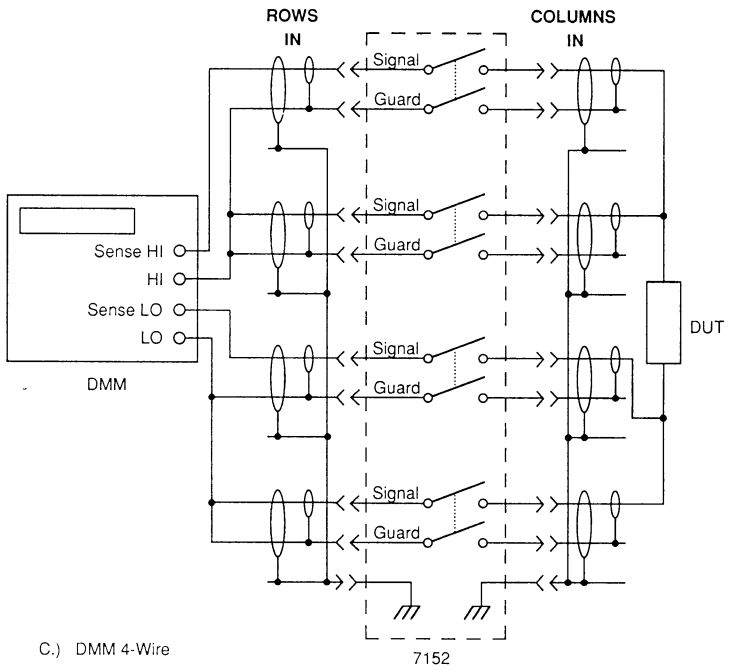


Warning : Hazardous voltage from guard sources may be present on LO.

Note : Use this configuration only for non-critical measurements.

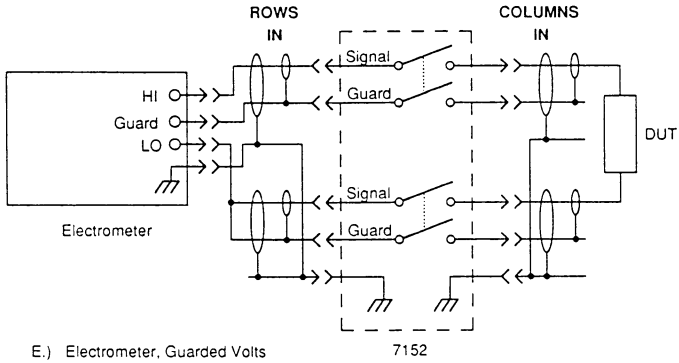
B.) DMM Common LO

Figure 2-9. General Instrument Connections

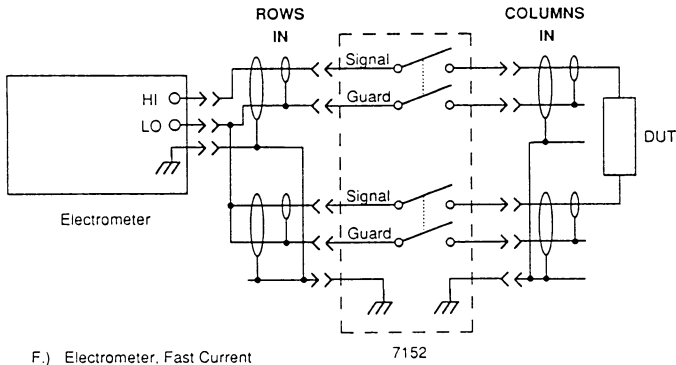


General Instrument Connections (Cont.)

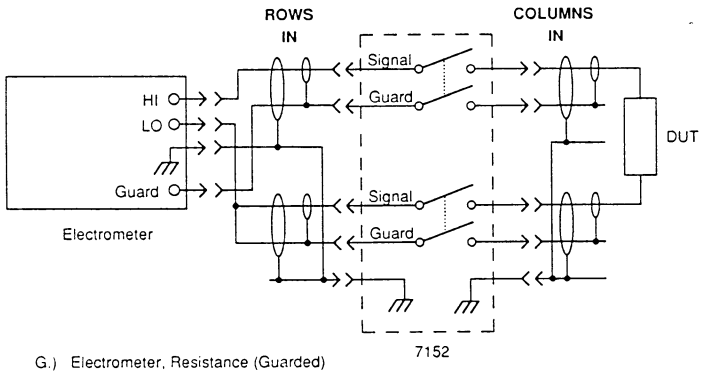
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E.) Electrometer, Guarded Volts

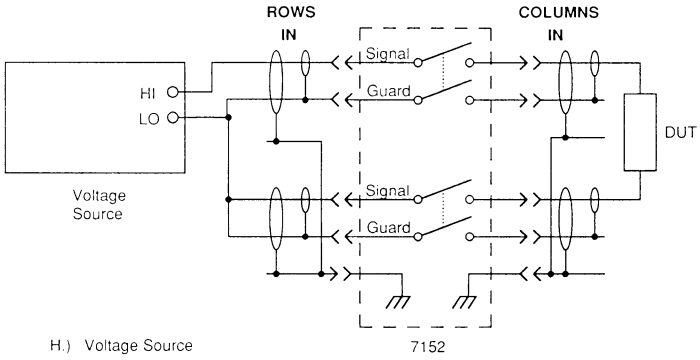


F.) Electrometer, Fast Current

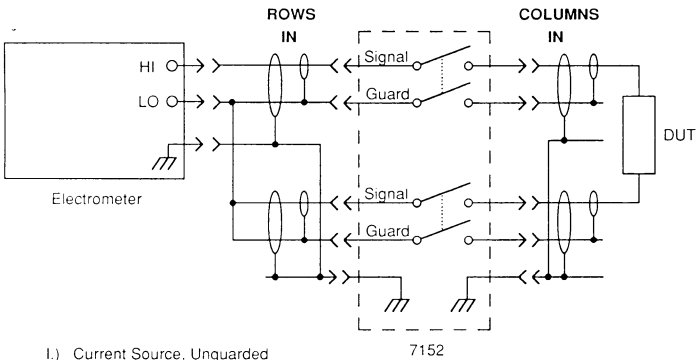


G.) Electrometer, Resistance (Guarded)

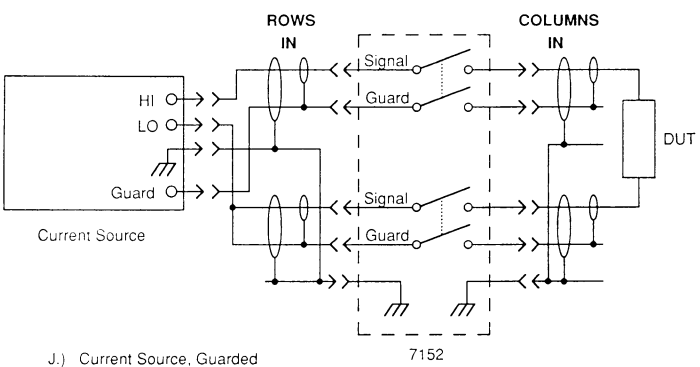
General Instrument Connections (Cont.)



H.) Voltage Source



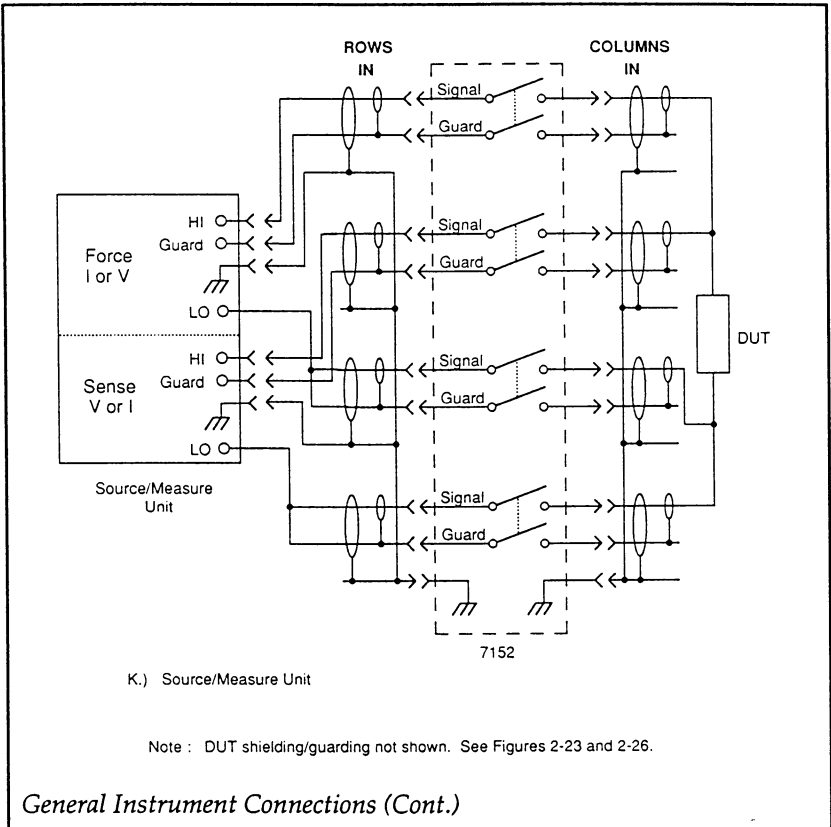
I.) Current Source, Unguarded



J.) Current Source, Guarded

General Instrument Connections (Cont.)

SECTION 2
Operation



2.6.5 Keithley Instrument Connections

The following paragraphs outline connecting typical Keithley instruments to the Model 7152 Low Current Matrix Card. Other similar instruments can be connected using the same cabling as long as their input/output configurations are the same. Instrument connections covered include:

- Model 617 Electrometer/Source
- Model 196 DMM
- Model 230 Programmable Voltage Source
- Model 220 Programmable Current Source

NOTE

The following figures show instruments connected to matrix rows. Keep in mind that they could just as well be connected to matrix columns. Also, it doesn't matter which rows (or columns) are used since the row/column specifications are uniform.

Model 617 Electrometer Connections

Connections for the Model 617 Electrometer are shown in Figure 2-10 and are described as follows:

1. Connect the matrix end of the Model 7152-TRX-10 cable assembly to ROW IN of the Model 7152.
2. Connect the Model 6172 2-slot male to 3-lug female triaxial adapter to the INPUT of the Model 617.
3. Connect Row 1 of the Model 7152-TRX-10 cable assembly to the triax adapter on the INPUT of the Model 617.

NOTE

The following connections require three triax to single banana cables that must be built. See paragraph 2.6.3 for details.

SECTION 2
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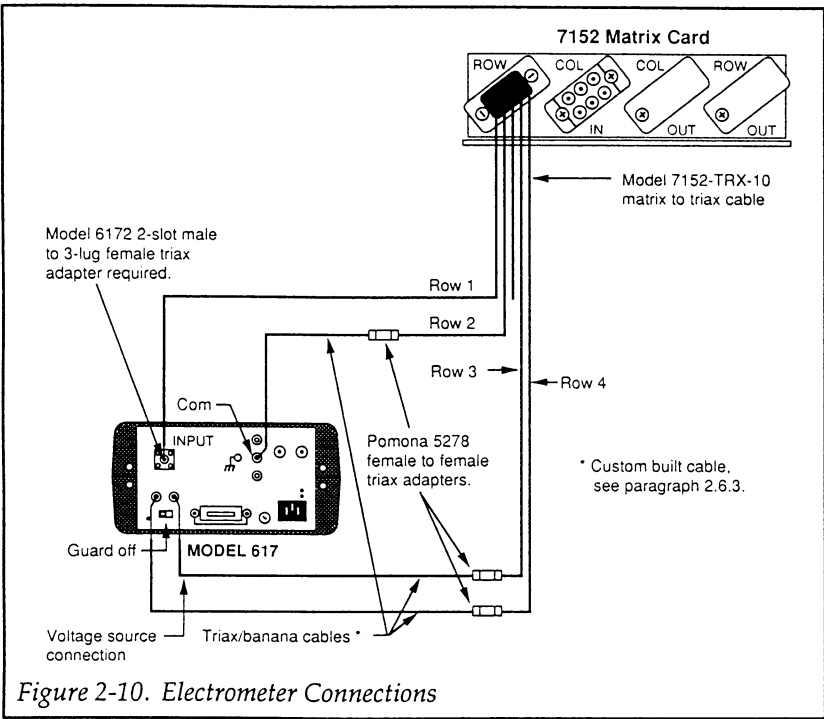


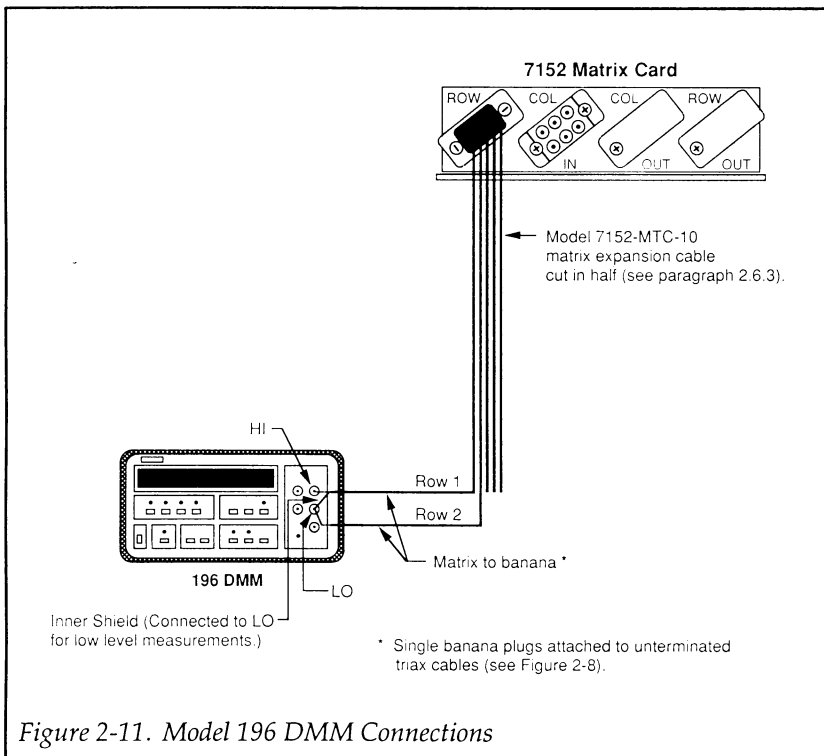
Figure 2-10. Electrometer Connections

4. Connect three 3-lug female to female triax adapters (item 4 in Table 2-1) to the three triax/banana cables.
5. Connect the triax adapter end of a triax/banana cable to Row 2 of the Model 7152-TRX-10, and connect the banana end of the cable to the COM terminal of the Model 617. The shorting link between COM and chassis ground should be removed for this application.
6. Set the Model 617 GUARD switch to the OFF position.
7. Connect the triax adapter end of the other two triax/banana cables to Rows 3 and 4 of the Model 7152-TRX-10 cable assembly, and connect the banana ends of the cables to the V-SOURCE HI and LO terminals of the Model 617.

Model 196 DMM Connections

Connect the Model 196 or other similar DMM to the matrix card using the general configuration shown in Figure 2-11. A Model 7152-MTC-10

matrix cable assembly that is cut in half and terminated with single banana plugs is used to make matrix connections to the VOLTS OHMS HI and LO terminals of the DMM. Matrix to banana cable preparation is detailed in paragraph 2.6.3.



For 4-wire ohms measurements, the OHMSENSE HI and LO terminals of the DMM should be connected to the two remaining rows of matrix card using the same matrix to banana cabling method.

NOTE

For low-level voltage measurements, connect the inner shield of the HI cable to VOLT OHMS LO to minimize noise.

Model 230 Voltage Source Connections

Referring to Figure 2-12, connect the Model 230 OUTPUT and COMMON terminals to the desired rows using a Model 7152-MTC-10 cable assembly that is cut in half and terminated with single banana plugs. Matrix to banana cable preparation is detailed in paragraph 2.6.3.

For remote sensing applications, the SENSE OUTPUT and SENSE COMMON terminals of the Model 230 can be connected to the two remaining rows using the same matrix to banana cabling method.

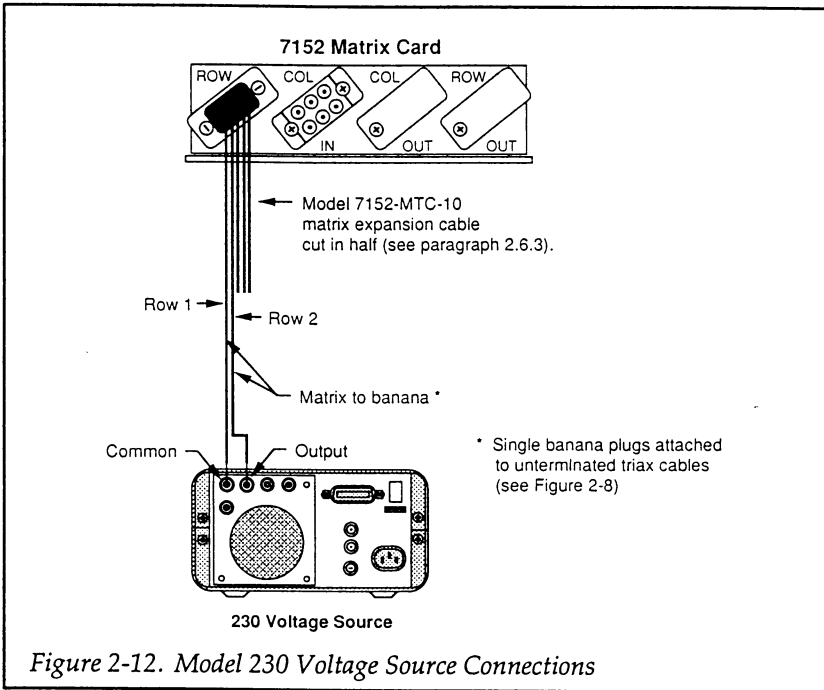
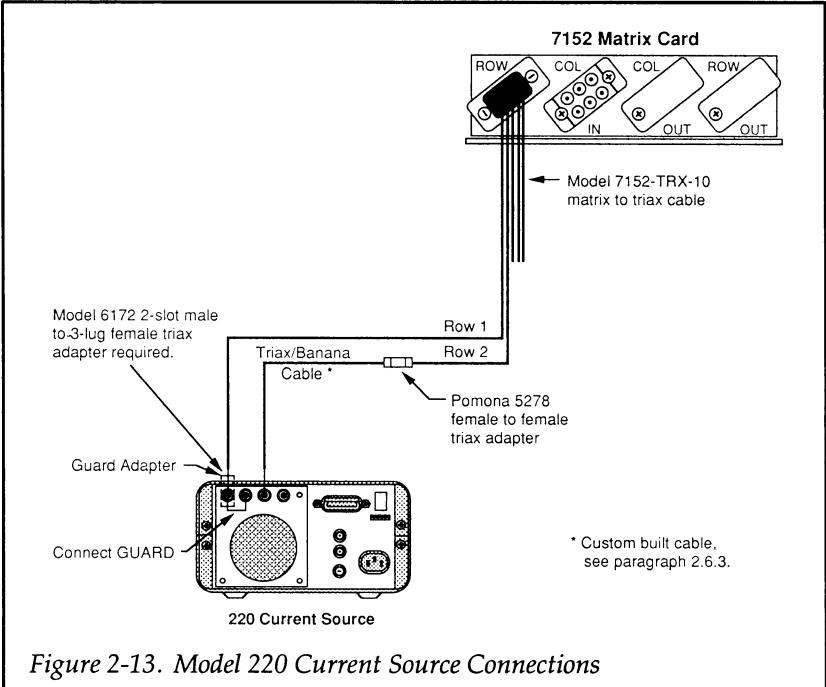


Figure 2-12. Model 230 Voltage Source Connections

Model 220 Current Source Connections

The Model 220 Current Source can be connected to the matrix card using the Model 6167 Guarded Adapter (item 7 in Table 2-1), as shown in

Figure 2-13. This configuration guards the output signal to minimize the effects of distributed capacitance and leakage current.



NOTE

The Model 6167 adapter must be modified by internally disconnecting the inner shield connection of the input jack from the GUARDED/UNGUARDED selection switch. Otherwise, instrument LO will be connected to chassis ground through the adapter.

1. Connect the matrix end of the Model 7152-TRX-10 cable assembly to ROW IN of the Model 7152.
2. Connect the Model 6167 adapter to the Model 220 OUTPUT jack.
3. Connect the Model 6172 (item 3 in Table 2-1) 2-slot male to 3-lug female triaxial adapter to the Model 6167 adapter.

4. Connect Row 1 of the Model 7152-TRX-10 cable assembly to the Model 6172 triax adapter.
5. Connect Model 6167 GUARD INPUT to GUARD OUTPUT of the Model 220.

NOTE

The following connections require a triax to single banana cable that must be built. See paragraph 2.6.3 for details.

6. Connect a 3-lug female to female triax adapter (item 4 in Table 2-1) to the triax/banana cable.
7. Connect the triax adapter end of the triax/banana cable to Row 2 of the Model 7152-TRX-10, and connect the banana end of the cable to the OUTPUT COMMON jack of the Model 220.

2.6.6 Typical Test Fixture Connections

Typically, a test fixture will be connected to desired columns of the Model 7152. Normally, the test fixture will be equipped with 3-lug female triax connectors to facilitate the use of the Model 7152-TRX-10 cable assembly. These typical test fixture connections are shown in Figure 2-14.

The Model 7152-MTC matrix to matrix cable assembly can also be used. To use this cable assembly, one of its plugs should be removed and the individual, unterminated cables would run through strain reliefs at the test fixture. Connections should then be made inside the test fixture. Cutting the Model 7152-MTC-10 in half will provide two five-foot cables that are unterminated at one end.

Another alternative is to equip the test fixture with subminiature coax, multiple contact receptacles (Model 7152-MTR). Model 7152-MTC cables can then be used to connect the matrix to the test fixture.

WARNING

Do not use BNC cables and adapters because hazardous voltages from guard sources could be present on the BNC cable shields.

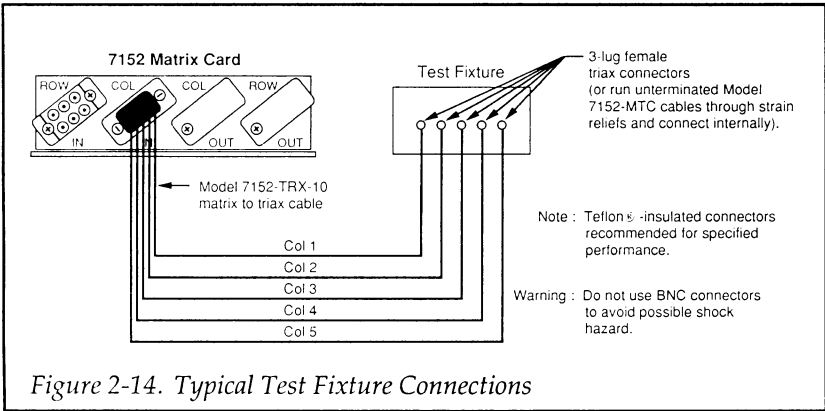


Figure 2-14. Typical Test Fixture Connections

Internally, the test fixture should be wired as shown in the equivalent circuit of Figure 2-15. SIGNAL is connected to the probe or other device contact points, while GUARD is carried through as close to the device as possible. If coaxial probes are to be used, connect GUARD to the probe shield if the probe shield is insulated from the fixture shield.

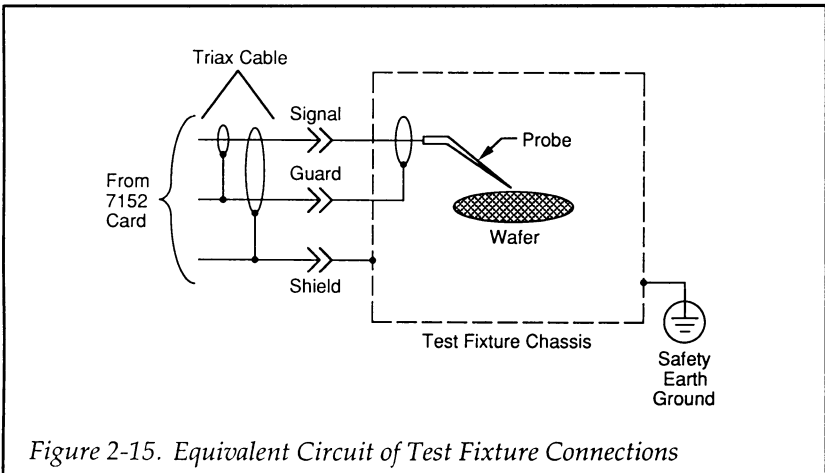



Figure 2-15. Equivalent Circuit of Test Fixture Connections

WARNING

To provide protection from shock hazards, the test fixture chassis must be properly connected to a safety earth ground. A grounding wire (18 AWG or larger) must be attached securely to the test fixture at a terminal designed for safety grounding (the terminal should be marked with the symbol ). The other end of the grounding wire is then attached to a known safety earth ground, such as a cold water pipe, or a grounded electrical outlet box.

2.7 MATRIX EXPANSION

A matrix can be expanded by connecting two or more Model 7152 matrix cards together. A single matrix card consists of 20 crosspoints. Thus, each additional matrix card increases the matrix by 20 crosspoints. Connecting the rows of one matrix card to the rows of another matrix card increases the number of matrix columns. Connecting the columns of one matrix card to the columns of another matrix card increases the number of matrix rows.

Using a single Model 705, a matrix consisting of two Model 7152 matrix cards (40 crosspoints) could be configured. With five Model 705s daisy chained, a matrix using 10 cards (200 crosspoints) could be configured. Using a single Model 706, a matrix consisting of 10 cards (200 crosspoints) could be configured. With five Model 706s daisy chained, a matrix using 50 cards (1000 crosspoints) could be configured.

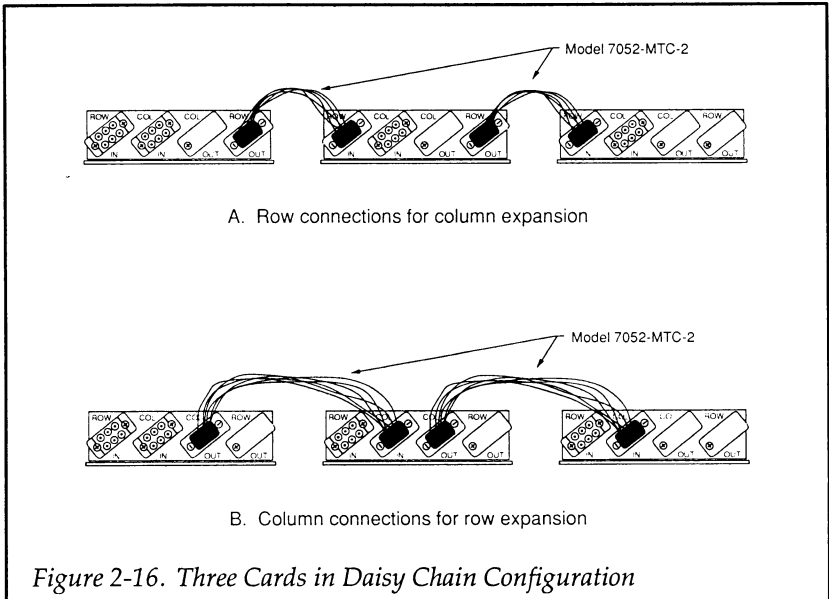
NOTE

Refer to the mainframe's instruction manual for information concerning daisy chain operation.

2.7.1 Matrix Expansion Connections

The Model 7152-MTC cables are used for matrix expansion. The plugs on these cables mate directly to the ROW and COLUMN receptacles on the Model 7152 matrix cards. To increase columns in a matrix, connect a Model 7152-MTC cable from ROW OUT of the first card to ROW IN of

the second card. ROW OUT of the second card is then connected to ROW IN of the next card, and so on. Figure 2-16A shows how the rows of three cards should be connected together. To increase rows in a matrix, the columns are connected in the same manner and are shown in Figure 2-16B. Note that the matrix cards in Figure 2-16 do not depict their actual physical orientation in a mainframe (Model 705 or 706). The illustration is intended only to clarify the daisy chain connections.



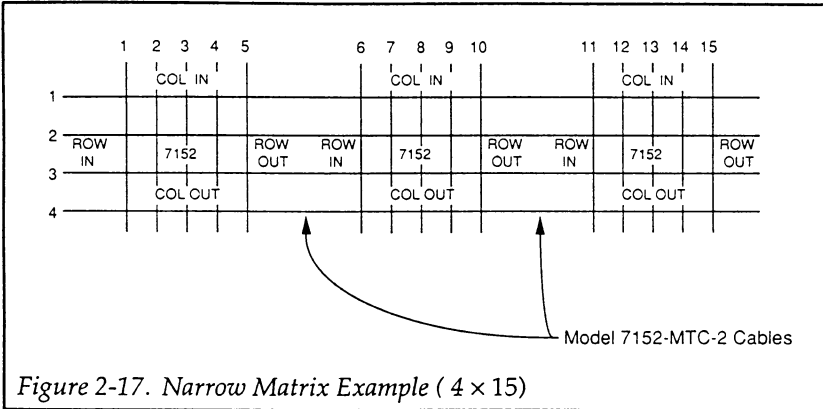
NOTE

In situations where path resistance is a consideration, use the shorter cables (Model 7152-MTC-2) for matrix expansion. This will help minimize path resistance.

2.7.2 Narrow Matrix Expansion

An example of a narrow matrix is shown in Figure 2-17. In this example, the rows of three matrix cards are daisy chained to configure a 4 × 15 ma-

trix. Two Model 7152-MTC-2 expansion cables are used for row connections.

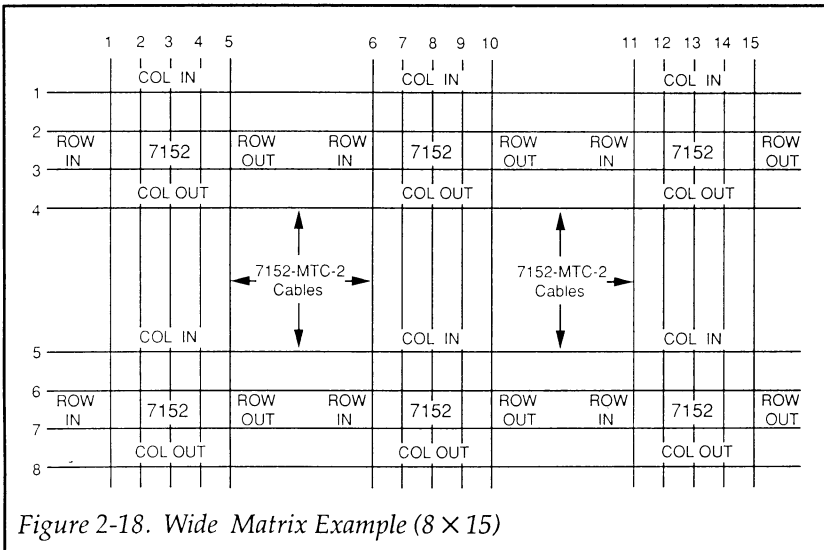


Using one Model 705, a 4 × 10 matrix could be configured. With the maximum of five Model 705s daisy chained, a 4 × 50 matrix could be configured. Using one Model 706, a 4 × 50 matrix could be configured. With the maximum of five Model 706s daisy chained, a 4 × 250 matrix could be configured.

2.7.3 Wide Matrix Expansion

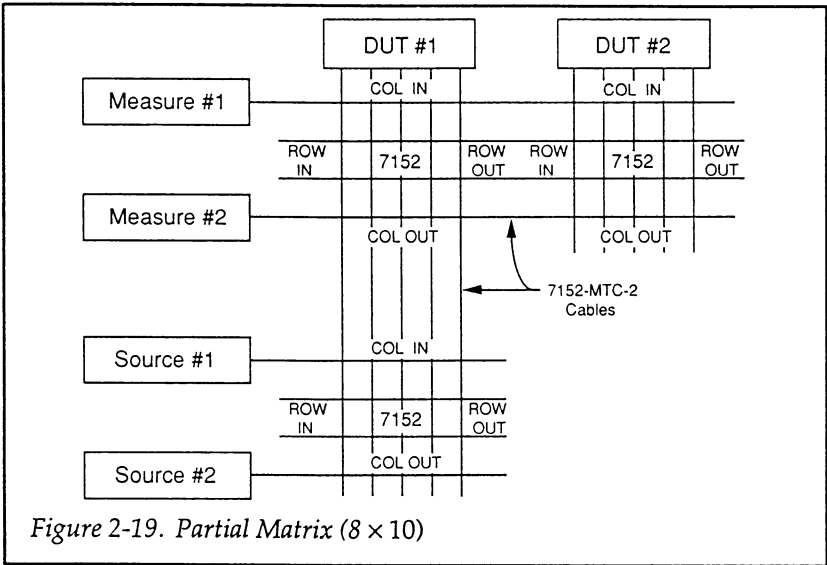
A wide matrix consists of eight or more rows. An example of a wide matrix is shown in Figure 2-18. In this example, rows and columns of six matrix cards are connected as shown to configure an 8 × 15 matrix. Notice that seven Model 7152-MTC-2 expansion cables are used for row and column connections.

It should be obvious that with multiple cards and daisy chained mainframes, numerous wide matrix configurations are possible. For example, with 50 matrix cards installed in five Model 706s that are daisy chained, a 20 × 50 matrix (5 cards × 10 cards) could be configured.



2.7.4 Partial Matrix Implementation

A fully implemented matrix provides a relay at each potential crosspoint. For example, a fully implemented 8 × 10 matrix utilizing four Model 7152s contains 80 crosspoints. A partially implemented matrix can be obtained by removing one Model 7152 from the system (see Figure 2-19). The partial matrix is still 8 × 10, but contains only 60 crosspoints. An obvious advantage of a partial matrix is that fewer matrix cards are needed. Another reason to use a partial matrix is to keep certain devices from being connected directly to other devices. For example, a source in Figure 2-19 cannot be connected to DUT #2 with one “accidental” crosspoint closure. Three specific crosspoints must be closed in order to connect a source to DUT #2.



2.7.5 Multiple Matrices

Two or more separate matrices can exist in the same test system. Figure 2-20 shows three separate matrices using ten matrix cards installed in the Model 706. Matrix A is a 4 × 25 matrix using Cards 1 through 5, Matrix B is a 4 × 15 matrix using Cards 6, 7 and 8, and Matrix C is a 4 × 10 matrix using Cards 9 and 10. Notice that there are no row or column connections between the three matrices. They are electrically isolated from each other even though they share the same mainframe.

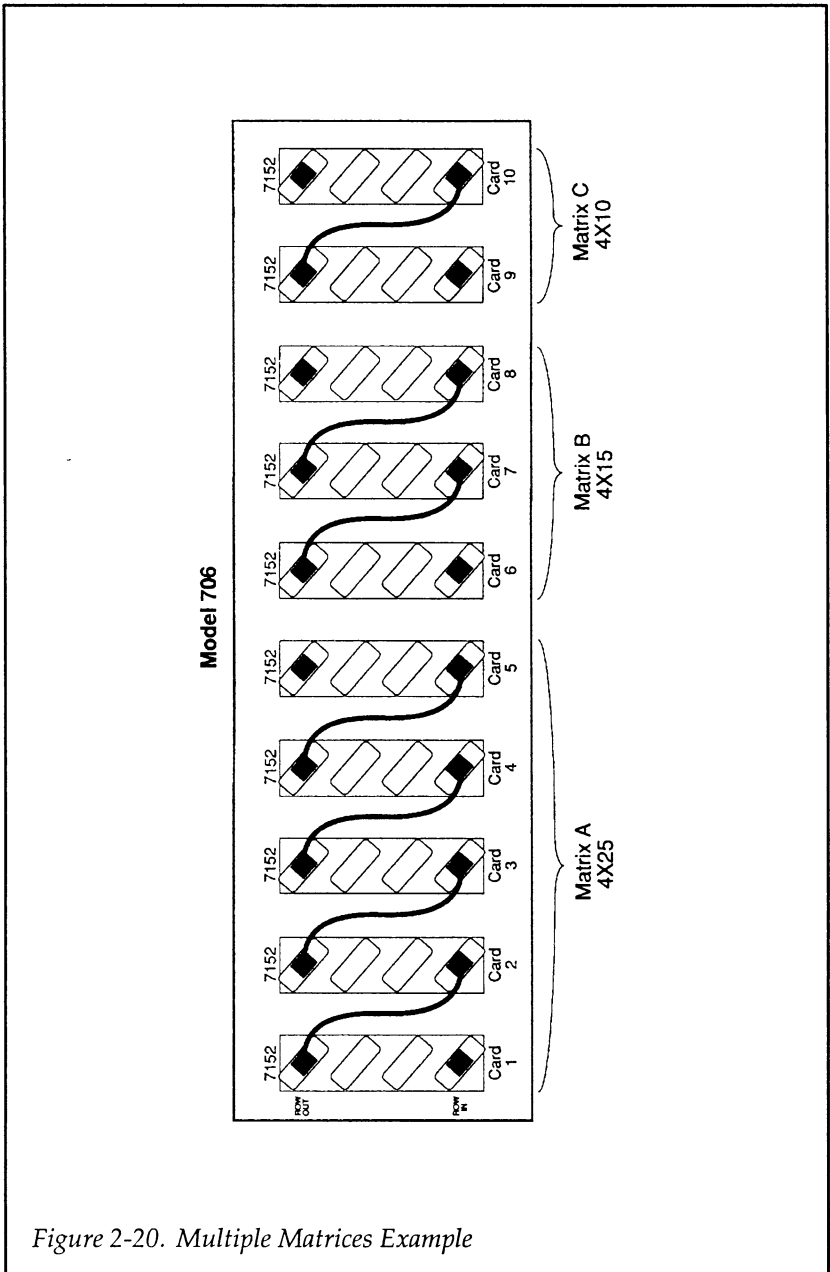


Figure 2-20. Multiple Matrices Example

2.8 MAINFRAME CONTROL OF MATRIX CARD

The information in the following paragraphs does not include operation of the Model 705 or 706 mainframe. That information is provided in the respective mainframe instruction manuals. The following deals primarily with programming information specific to controlling the Model 7152.

Whether from the front panel or over the IEEE-488 bus, matrix control is simply a matter of closing and opening the appropriate matrix crosspoints. Crosspoint assignment numbers for a Model 7152 card are determined by its installed position (card number) in a mainframe. For daisy chain operation, the position of the mainframe in the system is also a determining factor. The following paragraphs explain how to determine crosspoint assignment numbers.

2.8.1 Front Panel Matrix Control

Using the Model 7152 matrix card with an appropriate Keithley mainframe (Model 705 or 706) requires that the matrix mode be selected. To place the mainframe in the matrix mode from the front panel, perform the following steps:

1. Select Program 6 by pressing the PGRM key and then the number 6 key.
2. Press the 0 key and then the ENTER key.

After the ENTER key is pressed, the mainframe is placed in the matrix mode of operation.

With the mainframe in the matrix mode, the display format is as follows:

For the Model 705:

mm n x

where: “mm n” is the crosspoint assignment number.

mm = 2-digit ID number from 01 to 50. This number identifies the mainframe and slot that the card is located in and also indicates the matrix card column number.

n = Matrix card row from 1 to 4.

x denotes the status of the crosspoint. An O indicates that the crosspoint is open, while a C indicates that the crosspoint is closed.

For the Model 706:

mmm n x

where: “mmm n” is the crosspoint assignment number.

mmm = 3-digit ID number from 001 to 250. This number identifies the mainframe and slot that the card is located in and also indicates the matrix card column number.

n = Matrix card row from 1 to 4.

x denotes the status of the crosspoint. An O indicates that the crosspoint is open, while a C indicates that the crosspoint is closed.

In general, controlling the matrix from the front panel consists of displaying the desired matrix crosspoint assignment number and closing (or opening) the crosspoint relay. Table 2-2 and Table 2-3 provide the two-digit (for Model 705) and three-digit (for Model 706) ID numbers that make up the “m” portion of the crosspoint assignment number.

Table 2-2. Two-Digit ID Numbers for Programming Model 705

Model 705	Card Slot Location	Matrix Card Column				
		1	2	3	4	5
Master	Card 1	01	02	03	04	05
	Card 2	06	07	08	09	10
Slave #1	Card 1	11	12	13	14	15
	Card 2	16	17	18	19	20
Slave #2	Card 1	21	22	23	24	25
	Card 2	26	27	28	29	30
Slave #3	Card 1	31	32	33	34	35
	Card 2	36	37	38	39	40
Slave #4	Card 1	41	42	43	44	45
	Card 2	46	47	48	49	50

Table 2-3. Three-digit ID Numbers for Programming Model 706

Model 706	Card Slot Location	Matrix Card Column				
		1	2	3	4	5
Master	Card 1	001	002	003	004	005
	Card 2	006	007	008	009	010
	Card 3	011	012	013	014	015
	Card 4	016	017	018	019	020
	Card 5	021	022	023	024	025
	Card 6	026	027	028	029	030
	Card 7	031	032	033	034	035
	Card 8	036	037	038	039	040
	Card 9	041	042	043	044	045
	Card 10	046	047	048	049	050
Slave #1	Card 1	051	052	053	054	055
	Card 2	056	057	058	059	060
	Card 3	061	062	063	064	065
	Card 4	066	067	068	069	070
	Card 5	071	072	073	074	075
	Card 6	076	077	078	079	080
	Card 7	081	082	083	084	085
	Card 8	086	087	088	089	090
	Card 9	091	092	093	094	095
	Card 10	096	097	098	099	100
Slave #2	Card 1	101	102	103	104	105
	Card 2	106	107	108	109	110
	Card 3	111	112	113	114	115
	Card 4	116	117	118	119	120
	Card 5	121	122	123	124	125
	Card 6	126	127	128	129	130
	Card 7	131	132	133	134	135
	Card 8	136	137	138	139	140
	Card 9	141	142	143	144	145
	Card 10	146	147	148	149	150

Three-digit ID Numbers for Programming Model 706 (Cont.)

Model 706	Card Slot Location	Matrix Card Column				
		1	2	3	4	5
Slave #3	Card 1	151	152	153	154	155
	Card 2	156	157	158	159	160
	Card 3	161	162	163	164	165
	Card 4	166	167	168	169	170
	Card 5	171	172	173	174	175
	Card 6	176	177	178	179	180
	Card 7	181	182	183	184	185
	Card 8	186	187	188	189	190
	Card 9	191	192	193	194	195
	Card 10	196	197	198	199	200
Slave #4	Card 1	201	202	203	204	205
	Card 2	206	207	208	209	210
	Card 3	211	212	213	214	215
	Card 4	216	217	218	219	220
	Card 5	221	222	223	224	225
	Card 6	226	227	228	229	230
	Card 7	231	232	233	234	235
	Card 8	236	237	238	239	240
	Card 9	241	242	243	244	245
	Card 10	246	247	248	249	250

Example #1 — In a single card system, program the mainframe (Model 705 or 706) to close Row 3, Column 4 of a matrix card installed in the Card 1 slot of the mainframe.

1. From Table 2-2 or Table 2-3, it can be determined that the required ID number is 04 (for the Model 705) or 004 (for the Model 706).
2. From the given information, the row number is 3. Thus, the crosspoint assignment number is either 04 3 (for the 705) or 004 3 (for the 706).
3. On the mainframe, use the CHANNEL key to display the crosspoint assignment number (04 3 or 004 3).
4. Close the crosspoint relay by pressing the CLOSE key on the mainframe.

Example #2 — In a multi-mainframe system, program the Master mainframe (Model 705) to close Row 2, Column 4 of a matrix card installed in the Card 2 slot of Slave #3 mainframe.

1. From Table 2-2, it can be determined that the required two-digit ID number is 39.
2. From the given information, the row number is 2. Thus, the crosspoint assignment number is 39 2.
3. On the Master mainframe, use the CHANNEL key to display the number 39 2.
4. Close the crosspoint relay by pressing the CLOSE key on the Master mainframe.

Example #3 — In a multi-mainframe system, program the Master mainframe (Model 706) to close Row 2, Column 4 of a matrix card installed in the Card 2 slot of Slave #3 mainframe.

1. From Table 2-3, it can be determined that the required three-digit ID number is 159.
2. From the given information, the row number is 2. Thus, the crosspoint assignment number is 159 2.
3. On the Master mainframe, use the CHANNEL key to display the number 159 2.
4. Close the crosspoint relay by pressing the CLOSE key on the master mainframe.

2.8.2 Matrix Control Over IEEE-488 Bus

NOTE

Operation over the bus is somewhat analogous to front panel operation. Thus, to fully understand the information in this paragraph, make sure that front panel operation, as explained in the preceding paragraph, is understood.

The most often used IEEE-488 device-dependent commands (DDCs) used to operate the Model 7152 are summarized in Table 2-4. For a complete listing and detailed explanation of the commands, see the appropriate mainframe instruction manual.

Table 2-4. Most Often Used DDCs

DDC		Function
Model 705	Model 706	
A0	A0	Select matrix mode
Bmmn	Bmmm	Display crosspoint number
Cmmn	Cmmm	Close crosspoint
Nmmn	Nmmm	Open crosspoint

Note: mmn and mmmn are crosspoint assignment numbers (see paragraph 2.8.1).

Basically, control over the bus consists of first placing the mainframe in the matrix mode (A0 command) and then closing or opening the desired crosspoint using the C or N command respectively. The B command is used to display the crosspoint and its status (open or closed).

NOTE

The following programming examples use HP 4.0 BASIC. Also, they assume an IEEE address of 17 for the Model 705 and an address of 18 for the Model 706.

Example #1 — In a multi-mainframe system, program the master mainframe from (Model 705) over the IEEE bus to close Row 1, Column 5 of a matrix card installed in the Card 1 slot of Slave #4 mainframe.

1. From Table 2-2 it can be determined that the required two-digit ID number is 45.
2. From the given information, the row number is 1. Thus, the crosspoint assignment number is 45 1.
3. Enter the following programming statements into the HP computer:

```
REMOTE 717  
OUTPUT 717; "A0X"  
OUTPUT 717; "B451X"  
OUTPUT 717; "C451X"  
OUTPUT 717; "N451X"
```

The second statement places the master Model 705 in the matrix mode. The third statement displays crosspoint 45 1 and its current status (open or closed). The fourth statement closes crosspoint 45 1, and the last statement opens crosspoint 45 1.

Example #2 — In a multi-mainframe system, program the master mainframe (Model 706) from over the IEEE bus to close Row 4, Column 1 of a matrix card installed in the Card 8 slot of Slave #4 mainframe.

1. From Table 2-3 it can be determined that the required three-digit ID number is 236.
2. From the given information, the row number is 4. Thus, the crosspoint assignment number is 236 4.
3. Enter the following programming statements into the HP computer:

```
REMOTE 718  
OUTPUT 718; "A0X"  
OUTPUT 718; "B2364X"  
OUTPUT 718; "C2364X"  
OUTPUT 718; "N2364X"
```

The second statement places the master Model 706 in the matrix mode. The third statement displays crosspoint 236 4 and its current status (open or closed). The fourth statement closes crosspoint 236 4, and the last statement opens crosspoint 236 4.

2.9 MEASUREMENT CONSIDERATIONS

Many measurements made with the Model 7152 concern low-level signals. Such measurements are subject to various types of noise that can seriously affect low-level measurement accuracy. The following paragraphs discuss possible noise sources that might affect these measurements.

2.9.1 Magnetic Fields

When a conductor cuts through magnetic lines of force, a very small current is generated. This phenomenon will frequently cause unwanted signals to occur in the test leads of a switching matrix system. If the conductor has sufficient strength, even weak magnetic fields like those of the earth can create sufficient signals to affect low-level measurements.

Two ways to reduce these effects are: (1) reduce the lengths of the test leads, and (2) minimize the exposed circuit area. In extreme cases, magnetic shielding may be required. Special metal with high permeability at low flux densities (such as mu metal) are effective at reducing these effects.

Even when the conductor is stationary, magnetically-induced signals may still be a problem. Fields can be produced by various signals such as the ac power line voltage. Large inductors such as power transformers can generate substantial magnetic fields, so care must be taken to keep the switching and measuring circuits a good distance away from these potential noise sources.

2.9.2 Radio Frequency Interference

RFI (Radio Frequency Interference) is a general term used to describe electromagnetic interference over a wide range of frequencies across the spectrum. Such RFI can be particularly troublesome at low signal levels, but can also affect measurements at high levels if the problem is of sufficient severity.

RFI can be caused by steady-state sources such as radio or TV signals, or some types of electronic equipment (microprocessors, high speed digital circuits, etc.), or it can result from impulse sources, as in the case of arcing in high-voltage environments. In either case, the effect on the measurement can be considerable if enough of the unwanted signal is present. A common problem is the rectification by semiconductor junctions of RF picked up by leads.

RFI can be minimized in several ways. The most obvious method is to keep the equipment and signal leads as far away from the RFI source as possible. Shielding the matrix switching card, signal leads, sources, and measuring instruments will often reduce RFI to an acceptable level. In extreme cases, a specially-constructed screen room may be required to sufficiently attenuate the troublesome signal.

Many instruments incorporate internal filtering that may help to reduce RFI effects in some situations. In some cases, additional external filtering may also be required. Keep in mind, however, that filtering may have detrimental effects on the desired signal.

2.9.3 Ground Loops

When two or more instruments are connected together, care must be taken to avoid unwanted signals caused by ground loops. Ground loops usually occur when sensitive instrumentation is connected to other instrumentation with more than one signal return path such as power line ground. As shown in Figure 2-21, the resulting ground loop causes current to flow through the instrument LO signal leads and then back through power line ground. This circulating current develops a small but undesirable voltage between the LO terminals of the two instruments. This voltage will be added to the source voltage, affecting the accuracy of the measurement.

Figure 2-22 shows how to connect several instruments together to eliminate this type of ground loop problem. Here, only one instrument is connected to power line ground.

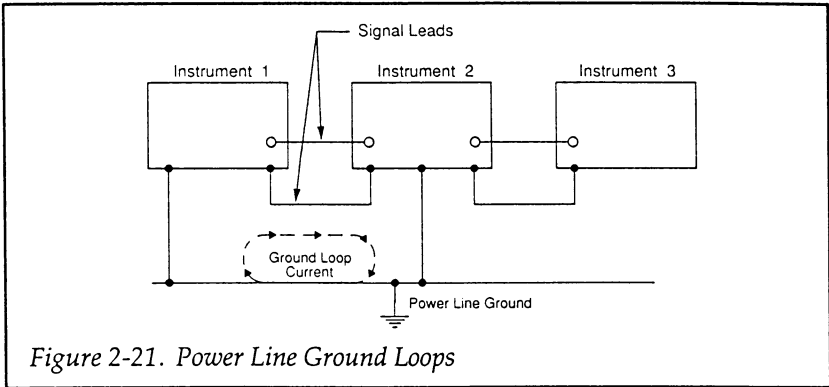


Figure 2-21. Power Line Ground Loops

Ground loops are not normally a problem with instruments having isolated LO terminals. However, all instruments in the test setup may not be designed in this manner. When in doubt, consult the manual for all instrumentation in the test setup.

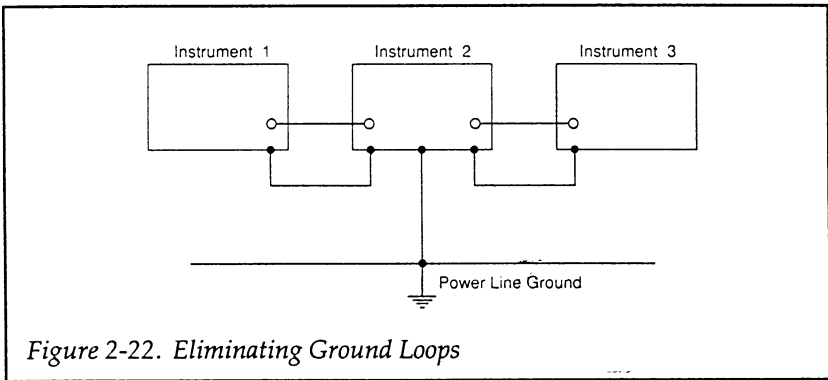


Figure 2-22. Eliminating Ground Loops

2.9.4 Keeping Connectors Clean

As is the case with any high-resistance device, the integrity of coaxial, triaxial and other connectors can be damaged if they are not handled properly. If the connector insulation becomes contaminated, the insulation resistance will be substantially reduced, affecting high-impedance measurement paths.

Oils and salts from the skin can contaminate connector insulators, reducing their resistance. Also, contaminants present in the air can be deposited on the insulator surface. To avoid these problems, never touch the connector insulating material. In addition, the matrix card should be used only in clean, dry environments to avoid contamination.

If the connector insulators should become contaminated, either by inadvertent touching, or from air-borne deposits, they can be cleaned with a cotton swab dipped in clean methanol. After thorough cleaning, they should be allowed to dry for several hours in a low-humidity environment before use, or they can be dried more quickly using dry nitrogen.

2.9.5 Noise Currents Caused by Cable Flexing

Noise currents can be generated by bending or flexing coaxial or triaxial cables. Such currents, which are known as triboelectric currents, are generated by charges created between a conductor and insulator caused by friction.

Low-noise cable can be used to minimize these effects. Such cable has a special graphite coating under the shield to provide lubrication and to provide a conduction path to equalize charges.

Even low-noise cable generates some noise currents when flexed or subjected to vibration. To minimize these effects, keep the cables as short as possible, and do not subject them to temperature variations that could cause expansion or contraction. Tie down offending cables securely to avoid movement, and isolate or remove vibration sources such as motors or pumps.

2.9.6 Shielding

Proper shielding of all unguarded signal paths and devices under test is important to minimize noise pickup in virtually any switching matrix system. Otherwise, interference from such noise sources as line frequency and RF fields can seriously corrupt a measurement.

In order for shielding to be effective, the shield surrounding the HI signal path should be connected to signal LO (or chassis ground for instruments without isolated LO terminals). Since most Model 7152 matrix applications call for separately switching LO, a separate connection from LO to the cable shield at the source or measurement end must be provided, as in the example of Figure 2-23. Here, we are using the GUARD path of the Model 7152 to carry the shield out to the device under test. Needless to say, this arrangement should not be used with guarding, as GUARD and LO should not be connected together.

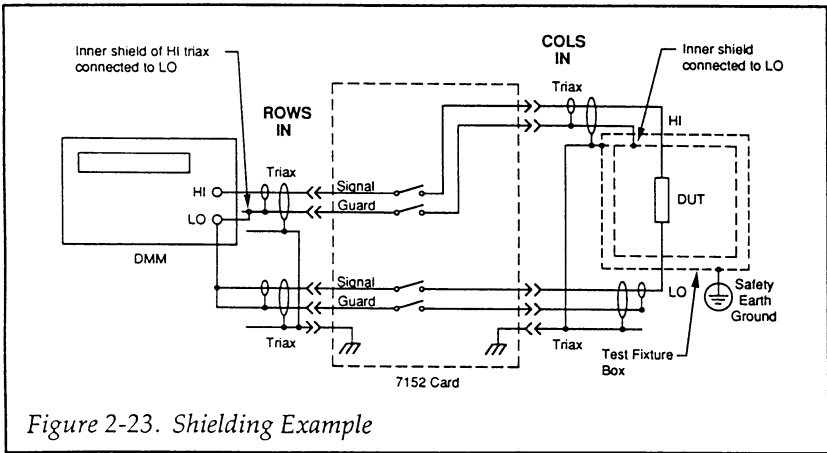


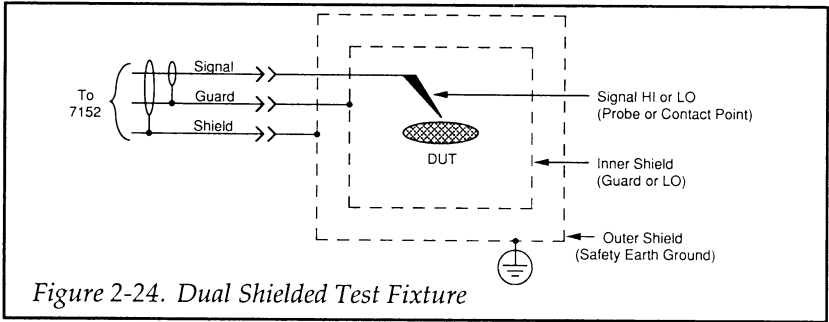
Figure 2-23. Shielding Example

WARNING

Hazardous voltage may be present if LO on any instrument is floated above ground potential.

If the device under test is to be shielded, the shield should be connected to the LO terminal. If you are using the GUARD connection as shield, care should be taken to insulate the outer ring of the triaxial connector mounted on the test fixture from the test fixture itself. Otherwise, LO will be connected to earth ground, possibly resulting in a ground loop. An alternative is to use two shields, one mounted within (and insulated from) the other. In this case, the GUARD path would be connected to the inner shield, while the outer shield would be earth grounded. This arrangement is shown in Figure 2-24. Incidentally, this configuration is

also recommended for guarded applications, with the inner shield as guard, and the outer shield acting as a safety shield.



2.9.7 Guarding

Guarding is important in high-impedance circuits where leakage resistance and capacitance could have degrading effects on the measurement. Guarding consists of using a shield surrounding a conductor that is carrying the high-impedance signal. This shield is driven by a low-impedance amplifier to maintain the shield at signal potential. For triaxial cables, the inner shield is used as guard.

Guarding minimizes leakage resistance effects by driving the cable shield with a unity-gain amplifier, as shown in Figure 2-25. Since the amplifier has a high input impedance, it minimizes loading on the high-impedance signal lead. Also, the low output impedance ensures that the shield remains at signal potential, so that virtually no leakage current flows through the leakage resistance, R_L . Leakage between inner and outer shields may be considerable, but that leakage is of little consequence because that current is supplied by the buffer amplifier rather than the signal itself.

In a similar manner, guarding also reduces the effective cable capacitance, resulting in much faster measurements on high-impedance circuits. Because any distributed capacitance is charged through the low impedance of the buffer amplifier rather than by the source, settling times are shortened considerably by guarding.

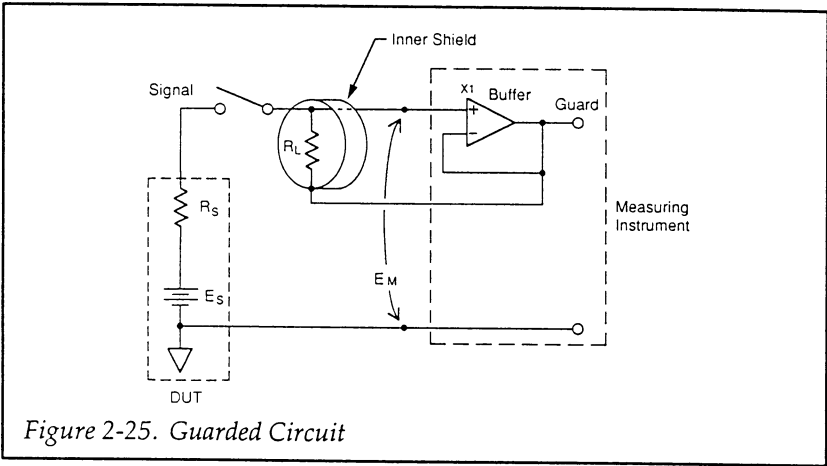
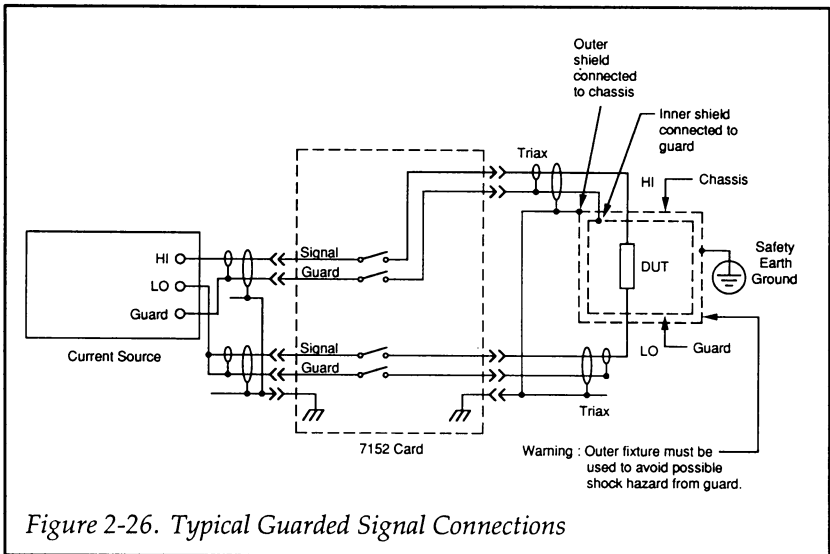


Figure 2-25. Guarded Circuit

In order to use guarding effectively with the Model 7152, the GUARD path of the matrix card should be connected to the guard output of the sourcing or measuring instrument. Figure 2-26 shows typical connections. Guard should be properly carried through the inner shield to the device under test to be completely effective. The shielded, guarded test fixture arrangement shown in Figure 2-24 is recommended for safety purposes (guard voltage may be hazardous with some instruments). With most instruments, special adapters or cables may be required to connect guard to the inner shield, and at the same time route signal LO through a separate cable.

2.9.8 Matrix Expansion Effects on Card Specifications

Specifications such as those given for path isolation and offset current are for a single Model 7152. Expanding the matrix by connecting two or more Model 7152 cards together will degrade system performance specifications. The extent depends on how many cards are used, as well as the amount of cabling used to connect them together.



With row or column expansion, isolation and offset current specifications are degraded because of the additional parallel paths and relays present on each signal line.

SECTION 3

Applications

3.1 INTRODUCTION

This section covers typical applications for the Model 7152 Low Current Matrix card and is organized as follows:

3.2 Semiconductor Test Matrix: Details a semiconductor test matrix that can be used to perform a variety of different tests on semiconductors such as FETs.

3.3 Resistivity Measurements: Covers methods to measure the resistivity of semiconductor samples using the van der Pauw method.

3.4 Semiconductor Parameter Analysis: Discusses using the Model 7152 in conjunction with an HP 4145B Semiconductor Parameter Analyzer.

3.2 SEMICONDUCTOR TEST MATRIX

Two important advantages of a matrix switching system are the ability to connect a variety instruments to the device or devices under test, as well as the ability to connect any instrument terminal to any device test node. The following paragraphs discuss a typical semiconductor matrix test system and how to use that system to perform a typical test: common-source characteristic testing of a typical JFET.

3.2.1 System Configuration

Figure 3-1 shows the configuration for a typical multi-purpose semiconductor test matrix. Instruments in the system perform the following functions.

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Applications

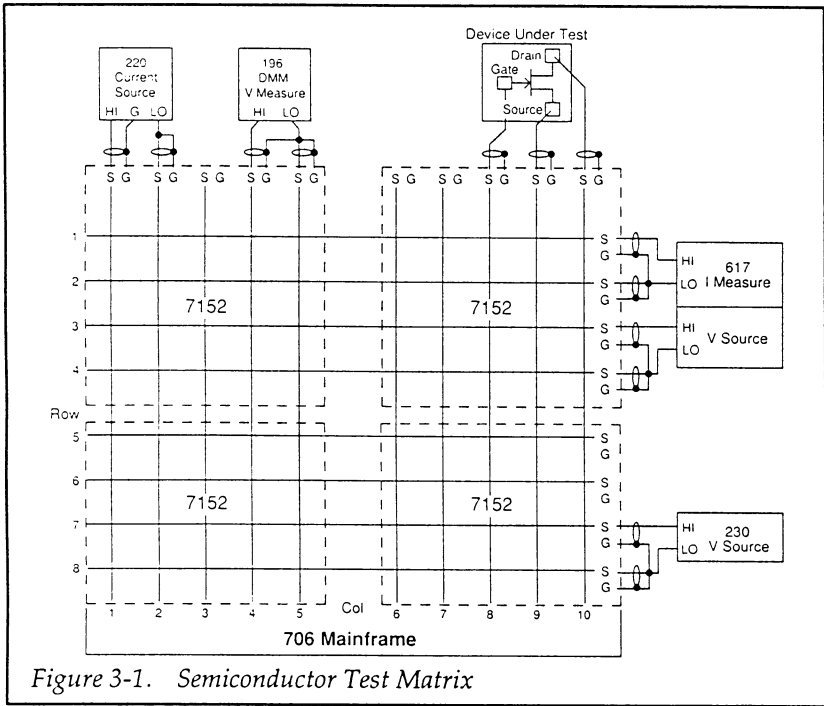


Figure 3-1. Semiconductor Test Matrix

Model 617 Electrometer/Source: Measures current, and also could be used to measure voltages up to $\pm 200\text{Vdc}$. The dc voltage source can supply a maximum of $\pm 100\text{V}$ at currents up to 2mA .

Model 230 Voltage Source: Sources dc voltages up to $\pm 101\text{V}$ at a maximum current of 100mA .

Model 220 Current Source: Used to source currents up to a maximum of 101mA with a maximum compliance voltage of 105V :

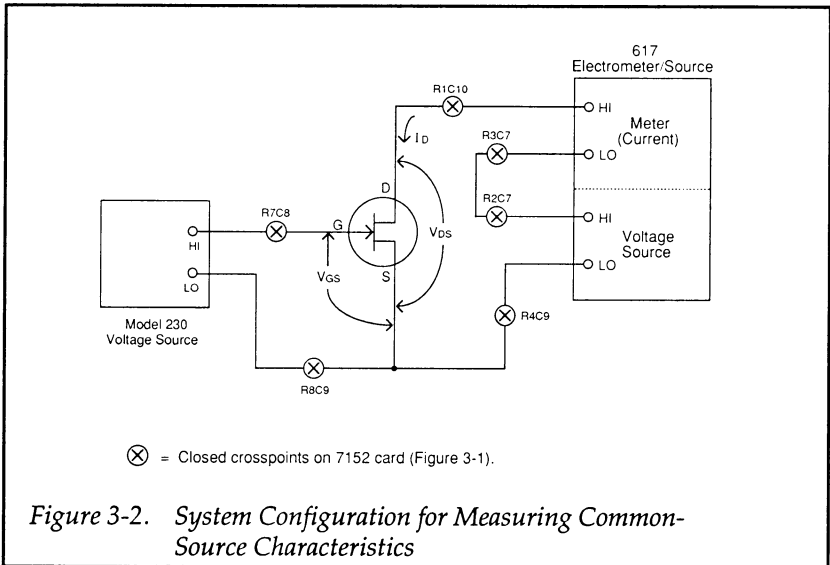
Model 196 DMM: Measure dc voltages in the range of 100nV to 300V . The Model 196 could also be used to measure resistance in certain applications.

Device Under Test: A three-terminal fixture for testing such devices as bipolar transistors and FETs. Additional connections could easily be added to test more complex devices, as required.

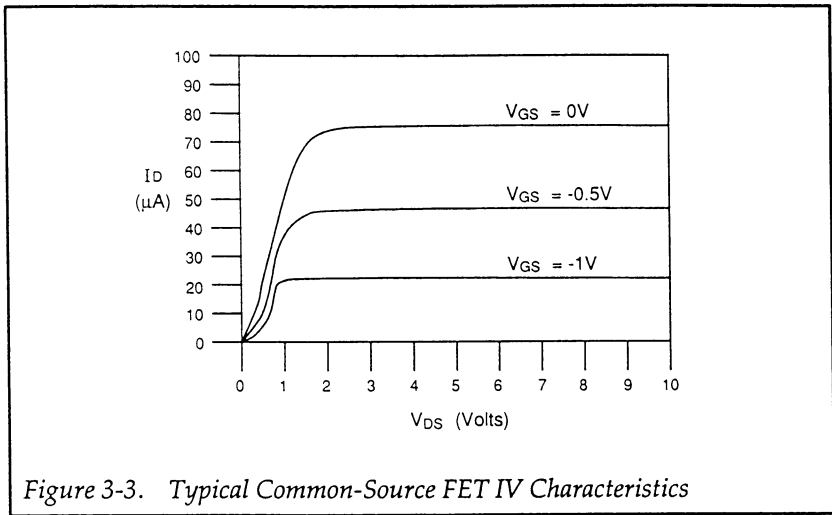
3.2.2 Testing Common-Source Characteristic of FETs

The system shown in Figure 3-1 could be used to test a variety of characteristics including I_{GSS} , $I_D(ON)$, I_{DSS} , and $V_{DS}(OFF)$. To demonstrate a practical use for the system, we will show how it can be used to generate common source characteristic curves of a particular JFET.

In order to generate these curves, the instruments must be connected to the JFET under test, as shown in Figure 3-2. The advantage of using the matrix is, of course, that it is a simple matter of closing specific crosspoints. The crosspoints that must be closed are also indicated on the diagram.



To run the test, V_{GS} is set to specific values, for example in increments of 0.25V. At each V_{GS} value, the drain-source voltage (V_{DS}) is stepped across the desired range, and the drain current, I_D , is measured at each value of V_{DS} . Once all data are compiled, it is a simple matter to generate the common-source IV curves, an example of which is shown in Figure 3-3. If the system is connected to a computer, the test and graphing could all be done automatically.



3.3 RESISTIVITY MEASUREMENTS

Model 7152 Semiconductor Matrix cards can be used in conjunction with a Model 220 Current Source and a Model 196 DMM to perform resistivity measurements on semiconductors. Such measurements can yield important information such as doping concentration.

3.3.1 Test Configuration

Figure 3-4 shows the basic test configuration to make resistivity measurements on van der Pauw samples. The Model 220 sources current through the samples, while the Model 196 measures the voltage developed across the samples. The matrix card, of course, switches the signal

paths as necessary. In order to minimize sample loading, which will reduce accuracy, the Model 196 DMM should be used only on the 300mV or 3V ranges. Also, this configuration is not recommended for resistance measurements above $1M\Omega$ due to the accuracy-degrading effects of DMM loading.

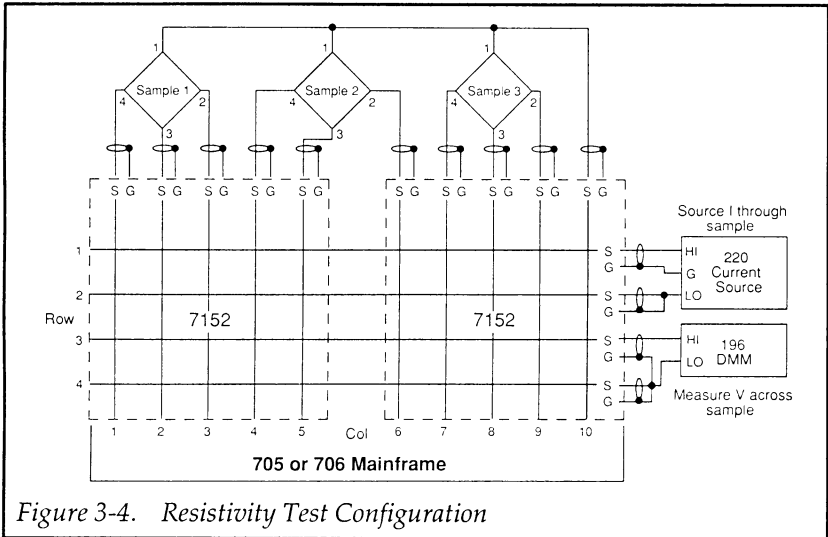


Figure 3-4. Resistivity Test Configuration

3.3.2 Test Procedure

In order to make van der Pauw resistivity measurements, four terminals of a sample of arbitrary shape are measured. A current (from the Model 220) is applied to two terminals, while the voltage is measured (by the Model 196) across the two opposite terminals, as shown in Figure 3-5. A total of eight such measurements on each sample are required, with each possible terminal and current convention. The resulting voltages are designated V_1 through V_8 .

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Applications

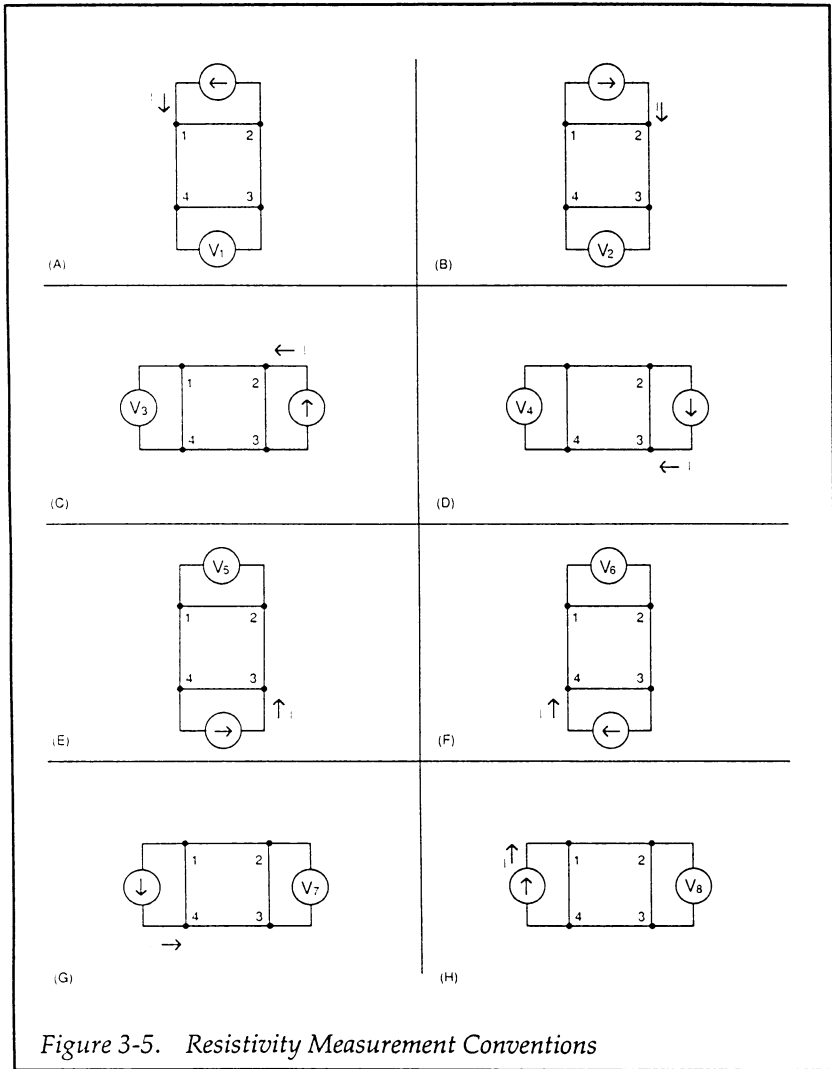


Figure 3-5. Resistivity Measurement Conventions

In order to source current into and measure the voltage across the sample, specific crosspoints must be closed. Table 3-1 summarizes the crosspoints to close for each voltage measurement on all three samples from the test configuration shown in Figure 3-4.

Table 3-1. Crosspoint Summary for Resistivity Measurements

Voltage	Crosspoints Closed Sample #1				Current Between	Voltage Between
V1	R1C10	R2C3	R3C2	R4C1	1-2	3-4
V2	R1C3	R2C10	R3C2	R4C1	2-1	3-4
V3	R1C3	R2C2	R3C1	R4C10	2-3	4-1
V4	R1C2	R2C3	R3C1	R4C10	3-2	4-1
V5	R1C2	R2C1	R3C10	R4C3	3-4	1-2
V6	R1C1	R2C2	R3C10	R4C3	4-3	1-2
V7	R1C1	R2C10	R3C3	R4C2	4-1	2-3
V8	R1C10	R2C1	R3C3	R4C2	1-4	2-3

Crosspoint Summary for Resistivity Measurements (Cont.)

Voltage	Crosspoints Closed Sample #2				Current Between	Voltage Between
V ₁	R1C10	R2C6	R3C5	R4C4	1-2	3-4
V ₂	R1C6	R2C10	R3C5	R4C4	2-1	3-4
V ₃	R1C6	R2C5	R3C4	R4C10	2-3	4-1
V ₄	R1C5	R2C6	R3C4	R4C10	3-2	4-1
V ₅	R1C5	R2C4	R3C10	R4C6	3-4	1-2
V ₆	R1C4	R2C5	R3C10	R4C6	4-3	1-2
V ₇	R1C4	R2C10	R3C6	R4C5	4-1	2-3
V ₈	R1C10	R2C4	R3C6	R4C5	1-4	2-3
Sample #3						
V ₁	R1C10	R2C9	R3C8	R4C7	1-2	3-4
V ₂	R1C9	R2C10	R3C8	R4C7	2-1	3-4
V ₃	R1C9	R2C8	R3C7	R4C10	2-3	4-1
V ₄	R1C8	R2C9	R3C7	R4C10	3-2	4-1
V ₅	R1C8	R2C7	R3C10	R4C9	3-4	1-2
V ₆	R1C7	R2C8	R3C10	R4C9	4-3	1-2
V ₇	R1C7	R2C10	R3C9	R4C8	4-1	2-3
V ₈	R1C10	R2C7	R3C9	R4C8	1-4	2-3

3.3.3 Resistivity Calculations

Once the eight voltage measurements are known, the resistivity can be calculated. Two values of resistivity, ρ_A and ρ_B are initially computed as follows:

$$\rho_A = \frac{1.1331 f_A t_S (V_2 + V_4 - V_1 - V_3)}{I}$$

$$\rho_B = \frac{1.1331 f_B t_S (V_6 + V_8 - V_5 - V_7)}{I}$$

Where:

ρ_A and ρ_B are the resistivities in $\Omega\text{-cm}$

t_S is the sample thickness in cm

V_1 through V_8 are the voltages measured by the Model 196

I is the current through the sample in amperes

f_A and f_B are geometrical factors based on sample symmetry ($f_A = f_B = 1$ for perfect symmetry).

Once ρ_A and ρ_B are known, the average resistivity, ρ_{AVG} , can be determined as follows:

$$\rho_{AVG} = \frac{\rho_A + \rho_B}{2}$$

3.4 SEMICONDUCTOR PARAMETER ANALYSIS

One or more Model 7152 matrix cards can be used in conjunction with an HP 4145B Semiconductor Parameter Analyzer (SPA) to provide a versatile switching system capable of complete dc characterization of semiconductors. The following paragraphs discuss system configuration, connections, and the SPA measurement considerations.

3.4.1 System Configuration

Figure 3-6 shows the general configuration of the SPA switching system. The components of the system perform the following functions:

HP 4145B: Has four SMUs (Source/Measure Units), two voltage sources, and two voltage measurement ports. The unit can automatically run a variety of tests on semiconductors and plot data on a built-in CRT.

Model 706 Scanner: Controls the matrix card to open and close signal paths as required.

Model 7152 Low Current Matrix Card: Switches the test pathways to the device under test. In this particular application, ten Model 7152s provide 25-pin test capability.

System Controller: Controls the SPA and switching matrix with user-written software. Typical controllers for this application are the HP 9000 Series 200 or 300 (with HP-IB interface), and IBM PC, AT or compatible computers (equipped with an IEEE-488 interface).

Test Fixture: Provides the interface between the device under test and the matrix card. Typically, the test fixture will be equipped with triax connectors for ease of connections.

3.4.2 Cable Connections

Figure 3-7 shows how to connect the HP 4145B to two Model 7152s. The four SMU ports are to be connected using the Model 7152-TRX cable as-

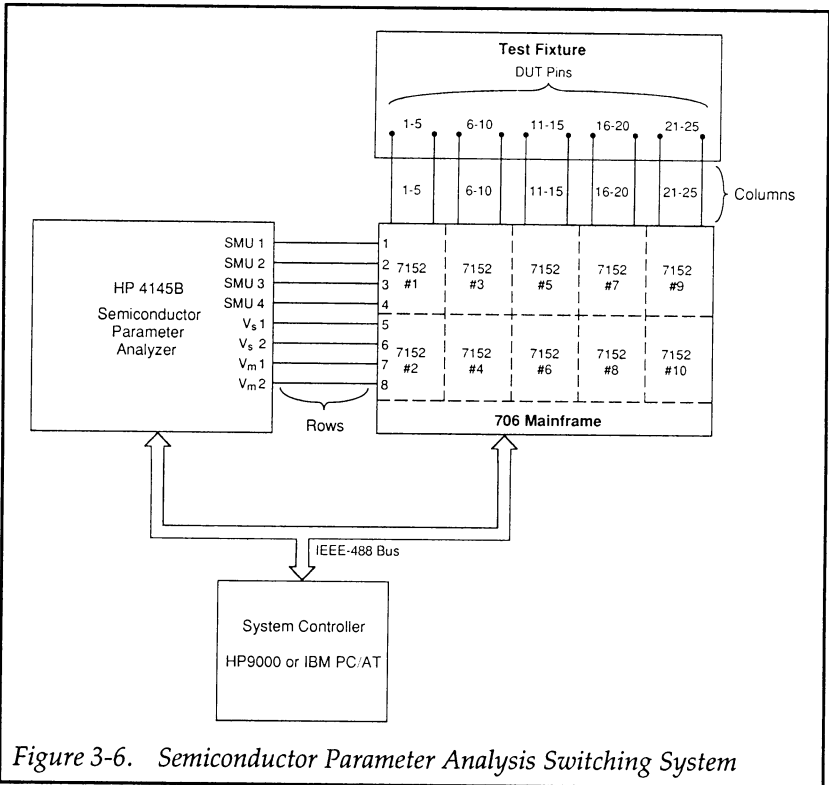


Figure 3-6. Semiconductor Parameter Analysis Switching System

sembly. The two voltage source and voltage measurement ports (V_s and V_m) are to be connected to the matrix card (#2) through another 7152-TRX using BNC cables (7051-10) and the adapters shown in the drawing. Typically, the SPA will be connected to the rows, as shown.

It is recommended that connections to a user-supplied test fixture be made using triax cables (such as the 7152-TRX-10) in order to maintain path integrity and safety. BNC cables and adapters should not be used in case hazardous potential appears on guard terminals.

WARNING

Hazardous voltage may be present on the outer conductors of the connecting cables when the HP 4145B is set up for

floating measurements. Carefully read the HP 4145B manual before using the system.

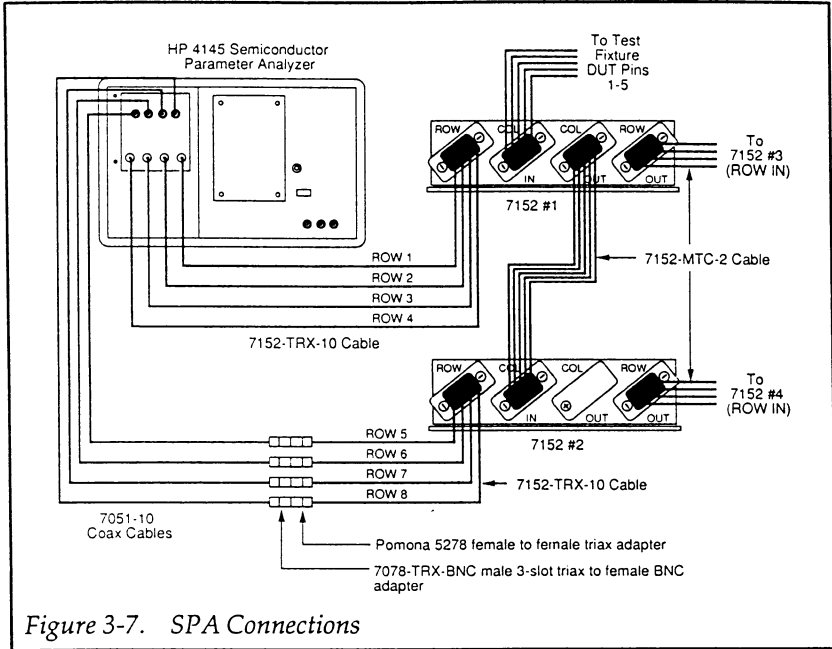


Figure 3-7. SPA Connections

3.4.3 Typical Test Procedure

The following paragraphs outline the procedure for using the SPA/matrix system to perform a typical test $V_{DS}-I_D$ (common-source) curves of a typical JFET. The procedure uses one of the four standard setups that are part of the applications package supplied with the HP 4145B.

System Configuration

Figure 3-8 shows the configuration and connections for this example. Only three of the four SMUs are required for the test, as indicated in the drawing. A total of three FETs can be connected to two cards, as shown

in the diagram. In all cases, triax cabling should be used. The crosspoints to close to test a specific FET are summarized in Table 3-2 .

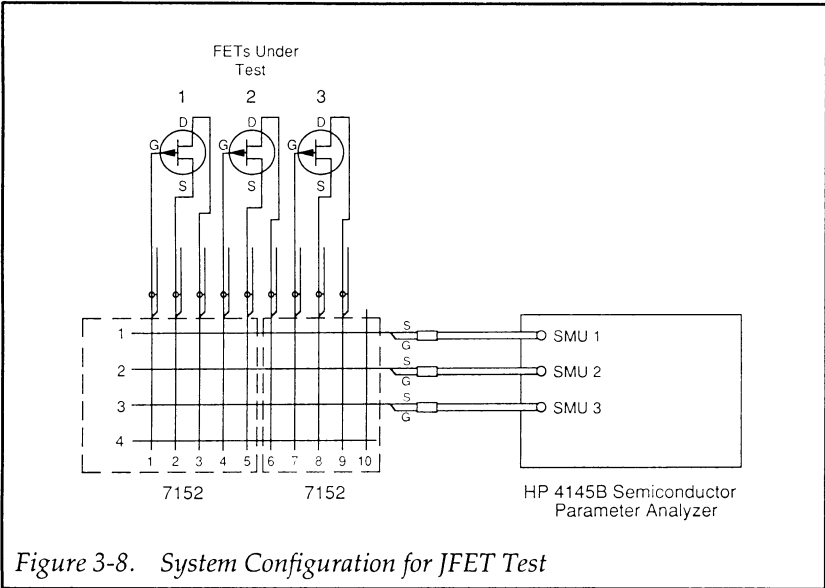


Figure 3-8. System Configuration for JFET Test

Table 3-2. Crosspoint Summary for JFET Test

JFET Tested	Crosspoints Closed* (Source, Gate, Drain)
1	R1C2 R3C1 R2C3
2	R1C5 R3C4 R2C6
3	R1C8 R3C7 R2C9

*See Figure 3-8.

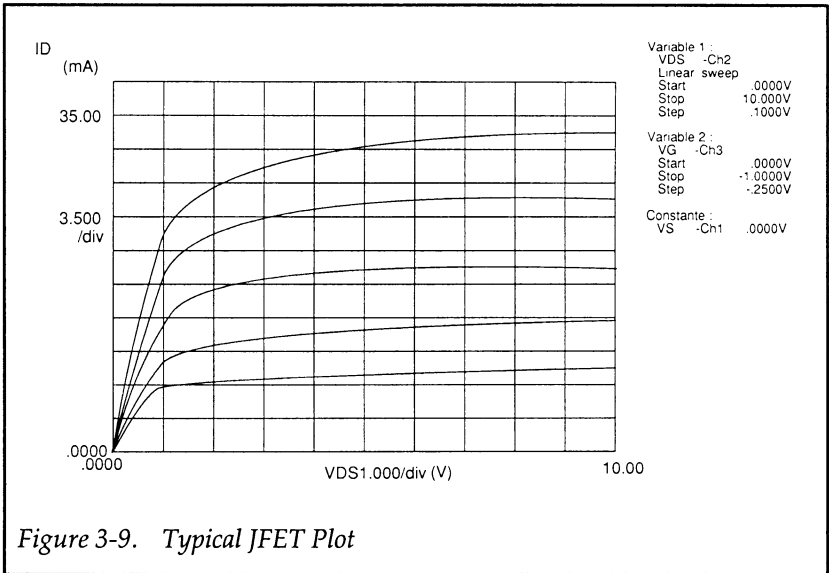
Procedure

1. Connect the system and devices as shown in Figure 3-8.
2. Turn on the Model HP 4145B and allow it to go through its boot-up routine.
3. Turn on the Model 706 mainframe.

4. From the HP 4145B main menu, select the channel definition page, then choose the FET V_{DS} - I_D application.
5. Press the PAGE NEXT key, and program the source parameters, as required.
6. Press the PAGE NEXT key, and program the required graphing parameters.
7. Press the PAGE NEXT key to display the graph format.
8. From the front panel of the Model 706, close the crosspoint necessary to connect the FET being tested to the SMUs (see Table 3-2).
9. Press the MEASUREMENT SINGLE key to initiate the sweep. The SPA will generate the I_D vs. V_{DS} curves at specified V_{GS} values.
10. Open the crosspoints presently closed.
11. Repeat steps 8 and 9 for the remaining devices, as required.

Typical Plot

Figure 3-9 shows a typical plot made using the procedure above. The device tested was a 2N4392 N-channel JFET. For the graphs, V_{DS} was swept from 0V to 10V in 1.1V increments, and V_{GS} was stepped from 0 to -0.25V.



REFERENCES

ASTM, F76-84. "Standard Method for Measuring Hall Mobility and Hall Coefficient in Extrinsic Semiconductor Single Crystals". Annual Bk. ASTM Stds., 1986: 10.05 155.

Coyle, G. et al, Switching Handbook. Keithley Instruments Inc., Cleveland, Ohio (1987).

Van der Pauw, L. J. "A Method of Measuring Specific Resistivity and Hall Effects of Discs of Arbitrary Shape". Philips Rec. Repts., 1958: 13 1.

Operation and Service Manual, Model 4145B Semiconductor Parameter Analyzer. Yokogawa-Hewlett-Packard Ltd, Tokyo, Japan (1982).

SECTION 4

Service Information

4.1 INTRODUCTION

This section contains information necessary to service the Model 7152 Low Current Matrix Card and is arranged as follows:

4.2 Handling and Cleaning Precautions: Discusses handling precautions and methods to clean the card should it become contaminated.

4.3 Performance Verification: Covers the procedures necessary to determine if the card is operating properly.

4.2 HANDLING AND CLEANING PRECAUTIONS

Because of the high-impedance circuits on the Model 7152, care should be taken when handling or servicing the card to prevent possible contamination. The following precautions should be taken when servicing the card.

1. Handle the card only by the edges. Do not touch any board surfaces or components not associated with the repair.
2. Do not store or operate the card in an environment where dust could settle on the circuit board. Use dry nitrogen gas to clean dust off the board if necessary.
3. Should it become necessary to use solder on the circuit board, remove the flux from the work areas when the repair has been completed. Use Freon® TMS or TE or the equivalent along with clean cotton swabs or a clean, soft brush to remove the flux. Take care not to spread the flux to other areas of the circuit board. Once the flux has been removed, swab only the repaired area with methanol, then blow dry the board with dry nitrogen gas.
4. After cleaning, the card should be placed in a 50°C low-humidity environment for several hours before use.

4.3 PERFORMANCE VERIFICATION

WARNING

The following test procedures should only be performed by qualified personnel who recognize shock hazards and are familiar with the safety precautions required to avoid possible injury.

The following paragraphs discuss performance verification procedures for the Model 7152, including offset (leakage) current, contact potential, path isolation, input isolation (differential and common mode), and path resistance.

All test procedures are to be performed with the Model 7152 installed in a Model 705 or 706 scanner mainframe. Also, the matrix card being checked must NOT be connected to any other card.

4.3.1 Environmental Conditions

All verification measurements except for isolation and offset current should be made at an ambient temperature between 0°C and 35°C and at a relative humidity of less than 70%. Path isolation, input isolation and offset current verification must be performed at an ambient temperature of 23°C and at a relative humidity of less than 60%. If the matrix card has been subjected to temperature or humidity extremes, allow the card to environmentally stabilize for at least one hour before performing any tests.

4.3.2 Recommended Test Equipment

Table 4-1 summarizes the equipment necessary to make the performance verification tests, along with the application for each item.

Table 4-1. Recommended Test Equipment

Manufacturer	Model or Part No.	Description	Applications
Keithley	617	Electrometer	Offset current and isolation
Keithley	181	Nanovoltmeter	Contact potential
Keithley	196	DMM	Path resistance
Keithley	705 or 706	Scanner main-frame	All tests
Keithley	7152-TRX-10	Matrix to Triax Cable	Offset current and path isolation
Keithley	6011	Triax to alligator clip cable	Common mode input isolation
Keithley	6012	Triax to UHF adapter	Differential input isolation
Keithley	6172	2-slot to 3-lug triax adapter	Offset current, path isolation and common mode input isolation
Keithley	CS-657	Guard terminal extender	Common mode input isolation and contact potential
—	—	Signal terminal extender (#26 AWG copper wire)	Contact potential
Keithley	1481	Low thermal input cable	Contact potential

Recommended Test Equipment (Cont.)

Manufacturer	Model or Part No.	Description	Applications
Keithley	7152-HCT	Coax crimping tool	Cable preparation
Pomona	5278	Female to Female triax adapter	Path Isolation
—	Special Connections	See Table 4-2	—

4.3.3 Special Connection Requirements

Many of the procedures in this section require special cables and connectors. The following provides the information needed to construct this equipment. The parts used to prepare this equipment are listed in Table 4-2.

Triax to Banana Cable

The procedure to construct this cable is found in paragraph 2.6.3. One triax/banana cable is required for the performance verification procedures.

Signal to Guard Shorting Plug

One low thermal shorting plug is required to check path resistance and contact potential. The shorting plug (see Figure 4-1) is built by modifying a subminiature coaxial connector pin. The short is accomplished by jamming a small length of #24 AWG copper wire between the center conductor (signal) and the outer casing (guard). The wire is then soldered to the connector pin.

Coax to Banana Cable

One coax/banana cable is required to check path resistance and differential input isolation. The coax/banana cable is shown in Figure 4-2. A

Table 4-2. Special Connection Parts

Description	Model or Part No.*	Application
Triax to Banana Cable Triax to Triax Cable (cut in half) Banana Plug	7078-TRX-10 BG-10-2	Path isolation
Signal to Guard Short Subminiature coax connector	CS-657	Contact potential and path resistance
Coax to Banana Cable Subminiature coax connector Coax Cable Banana plugs (2 required) Ferrule	CS-657 Belden® 9239 BG-10-2 FR-3	Differential input isolation
Signal Terminal Extender Subminiature coax connector Coax Cable Ferrule	CS-657 Belden® 9239 FR-3	Contact potential

*Keithley numbers except for the two Belden® entries.

subminiature coaxial female connector pin is connected to a suitable length of coaxial cable using the Model 7152-HCT crimping tool. Banana plugs are then connected to the other end of the cable as shown in the drawing. The cable should be kept as short as possible.

WARNING

High voltage will be present on the guard terminal when checking input isolation. To avoid electrical shock that could result in injury or death, make sure that the twisted braid (guard) of the cable is adequately insulated.

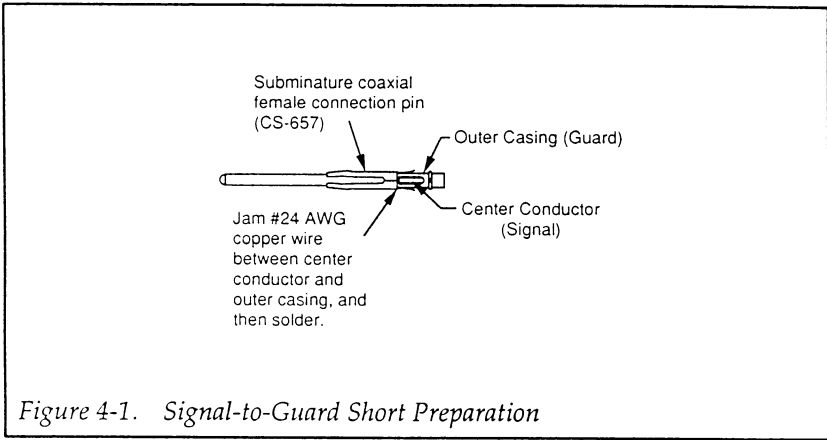


Figure 4-1. Signal-to-Guard Short Preparation

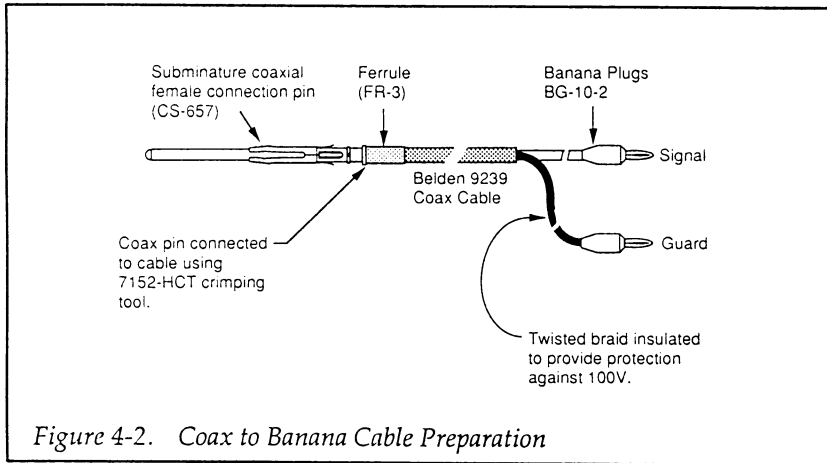
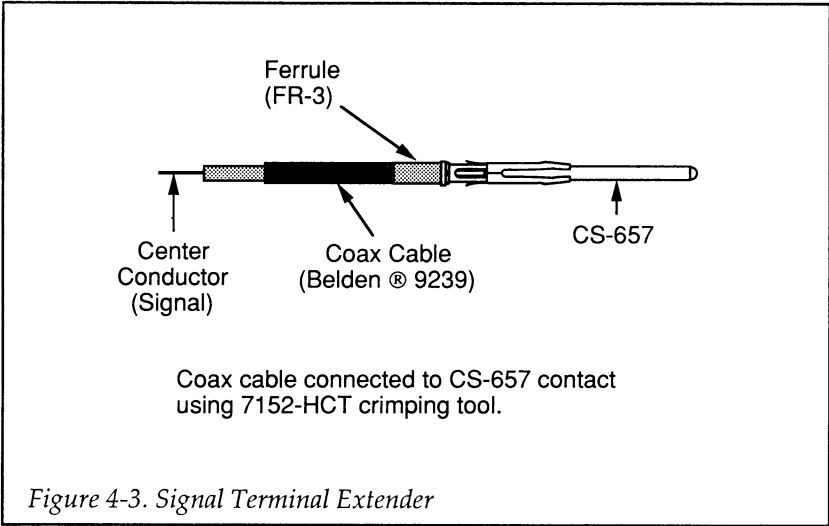


Figure 4-2. Coax to Banana Cable Preparation

Signal Terminal Extender

In order to check contact potential, a signal terminal extender is required. Figure 4-3 shows how a signal extender can be built. A suitable length of coaxial cable is connected to a female coaxial connector pin. A portion of the outer shield and inner insulator of the cable is then removed to expose a section of the center conductor (signal terminal).

Make sure the outer shield (guard) does not short out to the center conductor (signal).



4.3.4 Offset Current Verification

Recommended Equipment

- Keithley 617 Electrometer
- Keithley 7152-TRX-10 Matrix to Triax Cable
- Keithley 6172 2-slot to 3-lug triax adapter

Test Connections

Figure 4-4 shows the test connections for offset current verification. The Model 7152 row being tested is to be connected to the Model 617 Electrometer input as shown. Note that the electrometer ground strap is to be removed, and the electrometer should be operated in the unguarded mode.

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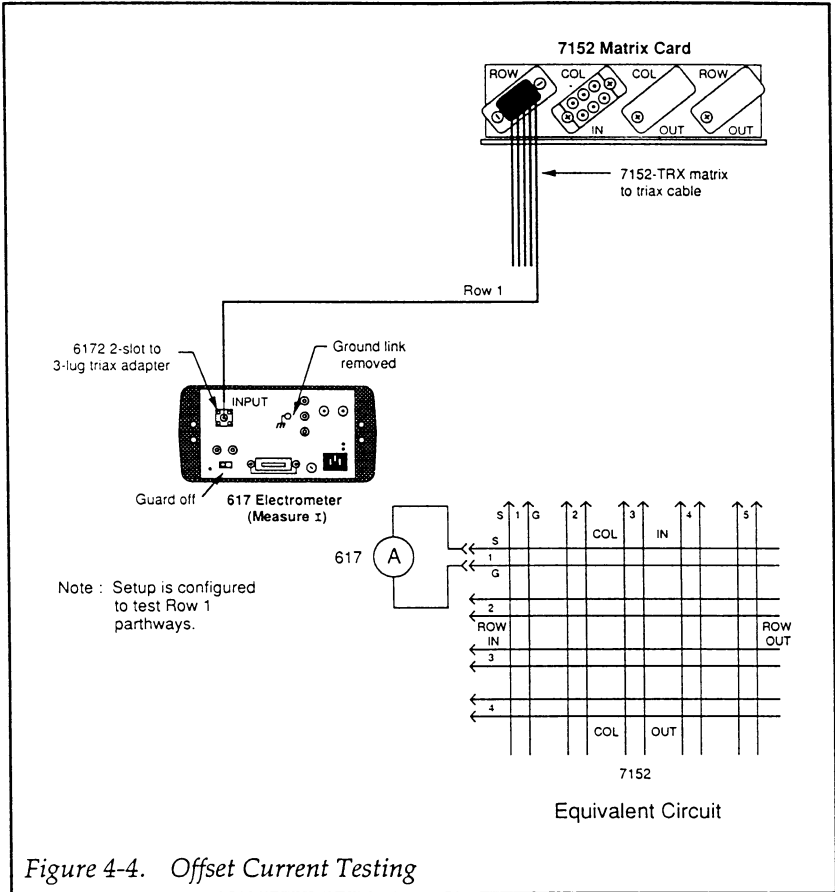


Figure 4-4. Offset Current Testing

Procedure

NOTE

The following procedure should be performed at an ambient temperature of 23°C and at a relative humidity of less than 60%.

1. Turn on the Model 617 power and allow it to warm up for two hours before beginning the verification procedure.

2. After the prescribed warm up period, select the amps function and the 2pA range on the Model 617. Zero correct the instrument, and then select autoranging.
3. Connect the Model 617 to row 1 of the Model 7152, as shown in Figure 4-4.
4. Close crosspoint R1C1 (row 1, column 1) by using the Model 705 or 706 front panel controls.
5. Disable zero check on the Model 617, and allow the reading to settle.
6. Verify that the offset current reading is <1pA.
7. Enable zero check on the Model 617, and open crosspoint R1C1.
8. Repeat steps 4 through 7 for crosspoints R1C2 through R1C5. Only one crosspoint at a time should be closed.
9. Disconnect the triax/banana cable from row 1, and connect it instead to row 2.
10. Repeat steps 4 through 7 for crosspoints R2C1 through R2C5. Only one crosspoint at a time should be closed.
11. On the Model 617, enable zero check.
12. Repeat steps 3 through 8 for rows 3 and 4. The electrometer should be connected to the row being tested, and only one crosspoint must be closed at a time.

4.3.5 Contact Potential Verification

Recommended Equipment

- Keithley 181 Nanovoltmeter
- Keithley Model 1481 Low Thermal Input Cable
- Signal to guard short (custom built; see Figure 4-1)
- Signal Terminal Extender (custom built; see Figure 4-3)
- Guard Terminal Extender (CS-657)

Test Connections

Figure 4-5 shows the test connections for contact potential verification.

Procedure

1. Turn on Model 181 power and allow it to warm up for one hour.

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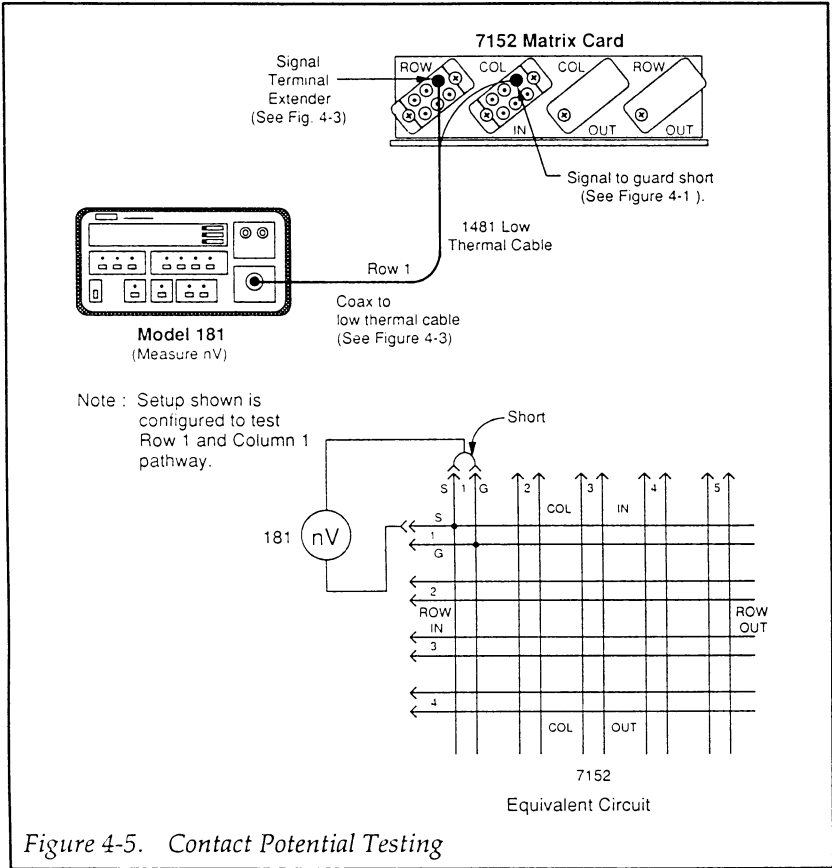


Figure 4-5. Contact Potential Testing

2. Connect the Model 1481 cable to the Model 181.
3. Connect the jumper to column 1 at the COL IN receptacle and install the Signal Terminal Extender in row 1 of the ROW IN receptacle.
4. After the prescribed warm up period, set the Model 181 to the 2mV range, short the alligator clips of the cable together, and press ZERO to null out internal offset. Leave ZERO enabled for the entire procedure.
5. Referring to Figure 4-5, connect the Model 181 to row 1 signal and column 1 jumper of the matrix card.
6. Program the mainframe to close crosspoint R1C1 (row 1, column 1).

7. Verify that the reading on the Model 181 is $<20\mu\text{V}$.
8. From the mainframe, open crosspoint R1C1 and move the jumper to column 2.
9. Repeat steps 6 through 8 to check the rest of the signal pathways (crosspoints R1C2 through R1C5) of the row. Only one crosspoint at a time should be closed.
10. Remove the Signal Terminal Extender from row 1 and install the Guard Terminal Extender.
11. Repeat step 6 through 9 to check the guard pathways of row 1.
12. Repeat steps 5 through 11 for rows 2 through 4. The nanovoltmeter should be connected to the row being tested and the jumper should be connected to the column being tested.

4.3.6 Path Isolation Verification

These tests check the leakage resistance (isolation) between adjacent matrix paths. Should the card fail any of the tests, clean it using the procedures outlined in paragraph 4.2.

Recommended Equipment

- Keithley 617 Electrometer
- Keithley 7152-TRX Matrix to Triax Cable
- Keithley 6172 2-slot to 3-lug triax adapter
- Pomona 5278 female to female triax adapter
- Triax to banana cable (custom built; see paragraph 2.6.3)

Test Connections

Figure 4-6 shows the test connections for the path isolation tests. One row being tested is to be connected to the Model 617 Electrometer input through a Model 6172 2-slot female to 3-lug male triaxial adapter. The other row is to be connected to the voltage source HI terminal using a specially prepared triax/banana cable, the construction of which is explained in paragraph 2.6.3. Note that both the inner shield and the center conductor are to be connected to the banana plug.

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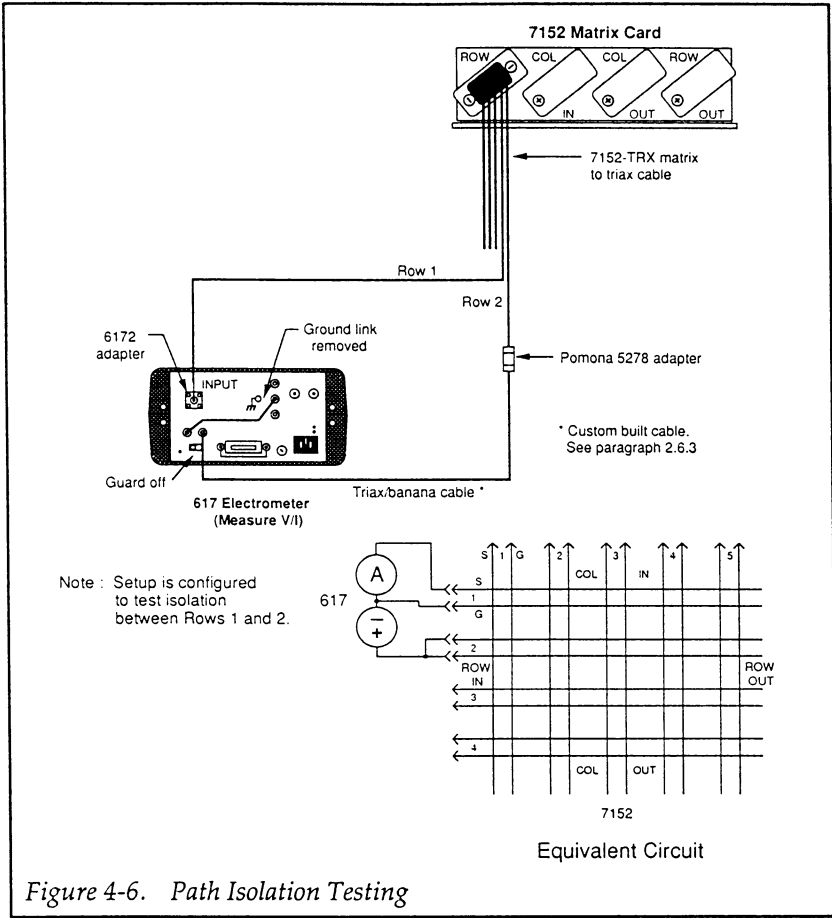


Figure 4-6. Path Isolation Testing

COM and the LO terminal of the electrometer voltage source must be connected together as shown. Also, the ground link between COM and chassis must be removed, and the Model 617 guard must be turned off for current measurements.

Procedure

WARNING

Hazardous voltage from the electrometer voltage source will be used in the following steps. Take care not to contact live circuits, which could cause personal injury or death.

NOTE

The following procedure must be performed at an ambient temperature of 23°C and at a relative humidity of less than 60%.

1. Turn on the Model 617 and allow it to warm up for two hours for rated accuracy.
2. After the prescribed warm up period, select the Model 617 amps function, and enable zero check. Select the 20pA range, and zero correct the instrument.
3. Connect the Model 617 to rows 1 and 2 of the matrix card, as shown in Figure 4-6.
4. Program the Model 617 voltage source for a value of +100V, but do not turn on the voltage source output.
5. Close crosspoints R1C1 (row 1, column 1) and R2C2 (row 2, column 2) from the mainframe.
6. With the Model 617 in amps, enable suppress after the reading has settled.
7. Turn on the Model 617 voltage source output, and enable the V/I ohms function on the electrometer.
8. After the reading has settled, verify that the resistance is $>10T\Omega$ ($10^{13}\Omega$).
9. Turn off the voltage source, and enable zero check. Disable suppress, and select the amps function on the electrometer.
10. From the front panel of the mainframe, press the RESET button to open all crosspoints.
11. Using Table 4-3 as a guide, repeat steps 5 through 10 for the crosspoint pairs listed starting with Test No. 2. Note that Model 617 is connected to rows 2 and 3 for tests 5 through 8, and connected to rows 3 and 4 for tests 9 through 12. Before moving the test connections, make sure the voltage source is off.

Table 4-3. Path Isolation Testing

Test No.	617 Connection		Crosspoint Pairs Closed	
	Electrometer Input	V-Source Output		
1 2 3 4	Row 1	Row 2	R1C1 R1C2 R1C3 R1C4	R2C2 R2C3 R2C4 R2C5
5 6 7 8	Row 2	Row 3	R2C1 R2C2 R2C3 R2C4	R3C2 R3C3 R3C4 R3C5
9 10 11 12	Row 3	Row 4	R3C1 R3C2 R3C3 R3C4	R4C2 R4C3 R4C4 R4C5

4.3.7 Differential Isolation Verification

These tests check the leakage resistance (isolation) between signal and guard of matrix pathways. Should the card fail any of the tests, clean it using the procedures outlined in paragraph 4.2.

Recommended Equipment

- Keithley 617 Electrometer
- Keithley 6012 Triax to UHF adapter
- Pomona 5278 female to female triax adapter
- Coax to banana cable (custom built; see Figure 4-2)

Test Connections

Figure 4-7 shows the test connections for the path isolation tests. The cable is connected to the row being tested. One banana plug (signal) of the cable is to be connected to the Model 617 Electrometer input through a Model 6012 triax to UHF adapter. The plug mates to the center conductor of the UHF voltage connector. The other banana plug (guard) connects to the electrometer voltage source.

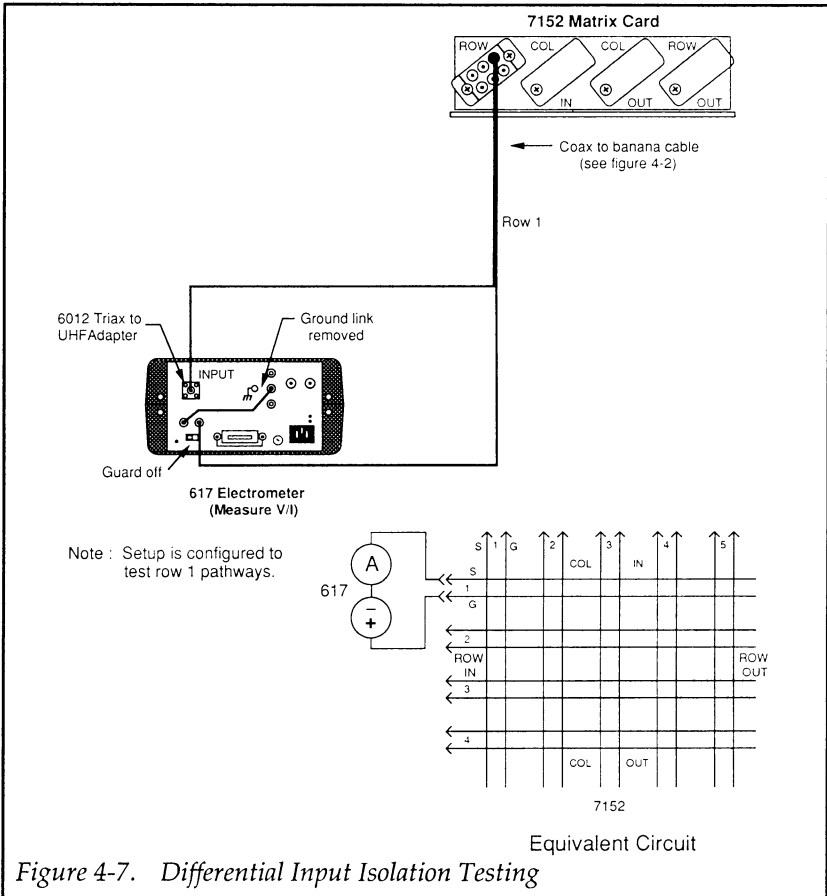


Figure 4-7. Differential Input Isolation Testing

COM and the LO terminal of the electrometer voltage source must be connected together as shown. Also, the ground link between COM and chassis must be removed, and the Model 617 guard must be turned off for current measurements.

Procedure

WARNING

Hazardous voltage from the electrometer voltage source will be used in the following steps. Take care not to contact live circuits, which could cause personal injury or death.

NOTE

The following procedure must be performed at an ambient temperature of 23°C and at a relative humidity of less than 60%.

1. Turn on the Model 617 and allow it to warm up for two hours for rated accuracy.
2. After the prescribed warm up period, select the Model 617 amps function, and enable zero check. Select the 2nA range, and zero correct the instrument.
3. Connect the Model 617 to row 1 of the matrix card, as shown in Figure 4-7.
4. Program the Model 617 voltage source for a value of +100V, but do not turn on the voltage source output.
5. Close crosspoint R1C1 (row 1, column 1) from the mainframe.
6. With the Model 617 in amps, enable suppress after the reading has settled.
7. Turn on the Model 617 voltage source output, and enable the V/I ohms function on the electrometer.
8. After the reading has settled, verify that the resistance is $>10\text{T}\Omega$ ($10^{13}\Omega$).
9. Turn off the voltage source, and enable zero check. Disable suppress, and select the amps function on the electrometer.
10. From the front panel of the mainframe, press the RESET button to open the crosspoint.
11. Connect the Model 617 to row 2 of the matrix card and repeat steps 5 through 10 for crosspoint R2C2.

12. Connect the Model 617 to row 3 of the matrix card and repeat steps 5 through 10 for crosspoint R3C3.
13. Connect the Model 617 to row 4 of the matrix card and repeat steps 5 through 10 for crosspoint R4C4.
14. With the electrometer still connected to row 4, repeat steps 5 through 10 for crosspoint R4C5.

4.3.8 Common Mode Isolation Verification

These tests check the leakage resistance (isolation) between signal/guard and chassis ground of matrix pathways. Should the card fail any of the tests, clean it using the procedures outlined in paragraph 4.2.

Recommended Equipment

- Keithley 617 Electrometer
- Keithley 6011 Triax to alligator clip cable
- Signal to guard short (custom built; see Figure 4-1)

Test Connections

Figure 4-8 shows the test connections for these tests. The Model 6011 cable is connected to the electrometer input as shown. The alligator clip on the black test lead of the cable is connected to the screw housing of the receptacle (chassis ground). The signal to guard short is installed in the row to be tested. The alligator clip on the red test lead is then connected to the short (signal/guard).

The Model 617 guard must be turned off for current measurements.

Procedure

NOTE

The following procedure must be performed at an ambient temperature of 23°C and at a relative humidity of less than 60%.

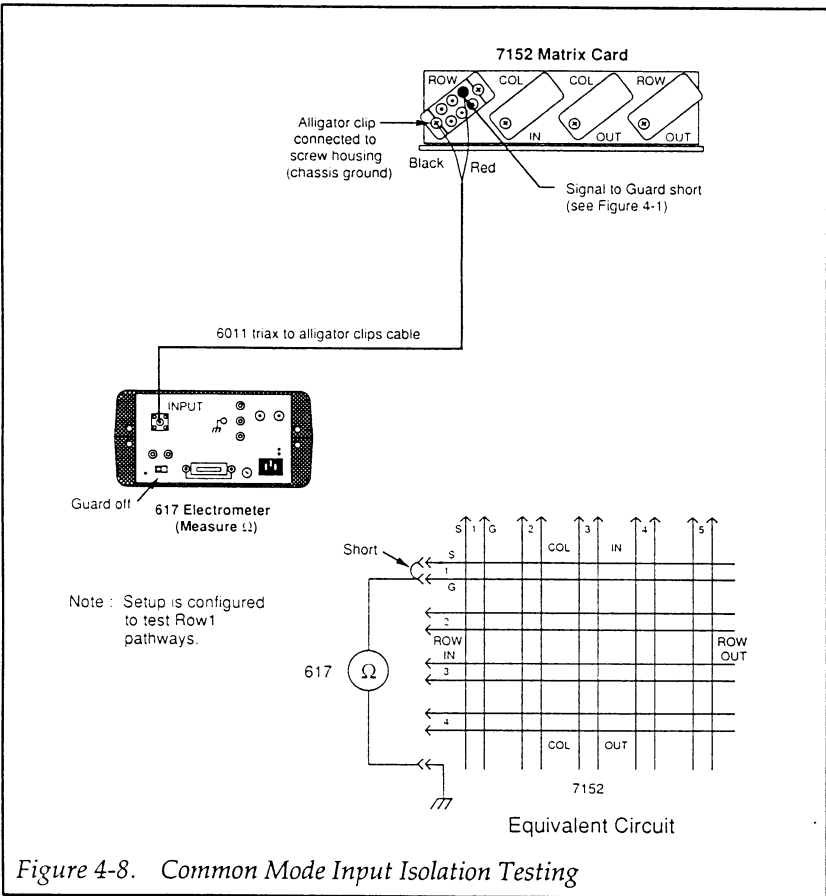


Figure 4-8. Common Mode Input Isolation Testing

1. Turn on the Model 617 and allow it to warm up for two hours for rated accuracy.
2. After the prescribed warm up period, select the Model 617 ohms function, enable zero check, and select the 10G Ω range.
3. Connect the Model 617 to row 1 and chassis ground of the matrix card, as shown in Figure 4-8.
4. Close crosspoint R1C1 (row 1, column 1) from the mainframe.
5. On the Model 617, release zero check. After the reading has settled, verify that the resistance is >1G Ω (10⁹ Ω).
6. On the Model 617, enable zero check.

7. From the front panel of the mainframe, press the RESET button to open the crosspoint.
8. Connect the short and red test lead from the Model 617 to row 2 of the matrix card and repeat steps 4 through 7 for crosspoint R2C2.
9. Connect the short and red test lead from the Model 617 to row 3 and repeat steps 4 through 7 for crosspoint R3C3.
10. Connect the short and red test lead from the electrometer to row 4 and repeat steps 4 through 7 for crosspoint R4C4.
11. With the electrometer still connected to row 4, repeat steps 4 through 7 for crosspoint R4C5.

4.3.9 Path Resistance Verification

The following paragraphs discuss the equipment, connections, and procedure to check path resistance. Should a particular pathway fail the resistance test, the relay (or relays) for that particular crosspoint is probably defective. See the schematic diagram at the end of Section 5 to determine which relay is defective.

Recommended Equipment

- Keithley 196 DMM
- Banana to clip-on test lead
- Coax to banana cable (custom built; see Figure 4-2)
- Signal to guard short (custom built; see Figure 4-1)

Connections

Figure 4-9 shows the connections for the path resistance tests. A specially prepared shorting plug is used to connect signal to guard, and is installed at the column being tested. The Model 196 low terminal is connected to the shorted column using the banana/clip-on test lead. This test lead clips onto the installed shorting plug. The high terminal of the DMM connects to the row being tested using the specially constructed coax/banana cable.

Procedure

1. Turn on the Model 196 DMM and allow it to warm up for at least one hour before beginning the test.

2. Using Figure 4-9 as a guide, connect the cable (signal) and test lead to the DMM, but do not make connections to the matrix card.
3. Temporarily clip the test lead to the inner conductor of the coax connector pin of the cable. This will short the DMM input.
4. Select the ohms function, 300 Ω range, and 5-1/2 digit resolution on the Model 196.
5. After the reading settles, enable zero on the Model 196 DMM. Leave zero enabled for the following tests.
6. Connect the cable and test lead to the matrix card as shown in Figure 4-9.
7. From the mainframe, close crosspoint R1C1 (row 1, column 1) and allow the reading to settle. Verify that the resistance reading is $< 2\Omega$.
8. On the mainframe, press the RESET button to open the crosspoint.
9. Repeat steps 7 and 8 for columns 2, 3 and 4. In each case the short and test lead must be connected to the column under test, and the crosspoint must be closed.
10. Repeat steps 7 through 9 for rows 2, 3 and 4. In each case, the electrometer is connected to the row under test. The crosspoint to close is the one corresponding to the row and column connections at that time. In all cases, the measured resistance should be $< 2\Omega$.
11. Disconnect the coax/banana cable from the matrix card and the DMM. Also, disconnect the clip-on test lead from the matrix card.
12. On the Model 196, disable zero.
13. Connect the guard banana plug of the cable to the HI terminal of the DMM. Do not make any connections to the matrix card.
14. Temporarily clip the test lead on to the outer shell of the coax connector pin of the cable. This will short the DMM input.
15. After the reading settles, enable zero on the Model 196. Leave zero enabled for the remaining tests.
16. Install the signal to guard shorting plug at column 1.
17. Connect the cable and test lead to the matrix card as shown in Figure 4-9. Note however, that guard (not signal as shown in the drawing) is to be connected to DMM HI.
18. Repeat steps 7 through 10 to test guard pathway resistance.

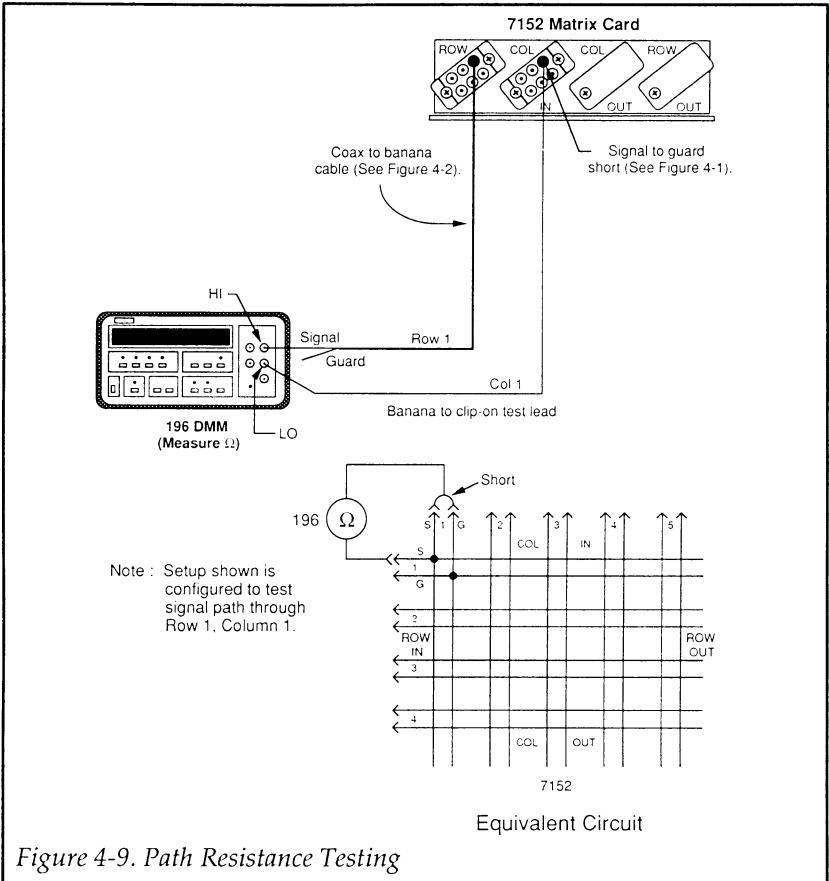


Figure 4-9. Path Resistance Testing

SECTION 5

Replaceable Parts

5.1 INTRODUCTION

This section contains a list of replaceable electrical and mechanical parts for the Model 7152, as well as a component layout drawing and schematic diagram of the card.

5.2 PARTS LIST

Electrical parts are listed in order of circuit designation in Table 5-1. Table 5-2 summarizes miscellaneous parts.

5.3 ORDERING INFORMATION

To place a parts order, or to obtain information concerning replacement parts, contact your Keithley representative or the factory (see the inside front cover for addresses). When ordering parts, be sure to include the following information:

1. Card model number
2. Card serial number
3. Part description
4. Circuit description, if applicable
5. Keithley part number

5.4 FACTORY SERVICE

If the card is to be returned to Keithley Instruments for repair, perform the following:

1. Complete the service form at the back of this manual and include it with the card.

2. Carefully pack the card in the original packing carton.
3. Write ATTENTION REPAIR DEPARTMENT on the shipping label.

5.5 COMPONENT LAYOUT AND SCHEMATIC DIAGRAM

A component layout of the Model 7152 is contained in drawing number 7152-100, while drawing number 7152-106 contains a schematic diagram.

TABLE 5-1. PARTS LIST

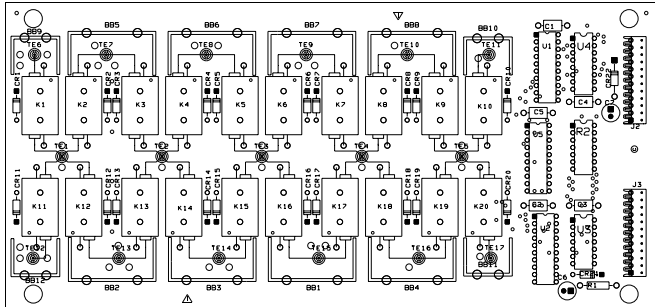
CIRCUIT DESIG.	DESCRIPTION	KEITHLEY PART NO.
C1..C5	CAP,.1uF,20%,50V,CERAMIC	C-365-.1
C6	CAP,22uF,-20+100%,25V,ALUM ELEC	C-314-22
C7	CAP,10uF,-20+100%,25V,ALUM ELEC	C-314-10
CR1..		
CR21	DIODE,SILICON,1N4148 (DO-35)	RF-28
J2,J3	CONNECTOR	CS-583-1
K1..		
K20	RELAY,REED	RL-124
P2,P3	CONNECTOR	CS-584-1
R1	RES,40.2K,1%,1/8W,METAL FILM	R-88-40.2K
R2	RES NET,4.7K,2%,1.5W	TF-19-4.7K
U1	IC,BUF/LINE DRIVER & RECEIVER, MC74HC241N	IC-520
U2,U5	IC,OCTAL TRI-STATE BUFFER, MM74HC240	IC-617
U3	IC,DUAL D-TYPE FLIP FLOP,74HC74	IC-337
U4	IC,8 STAGE SHIFT/STORE REGISTER, 4094	IC-251

TABLE 5-2. MISCELLANEOUS, PARTS LIST

QTY.	DESCRIPTION	KEITHLEY PART NO.
4	CONNECTOR HOUSING	CS-655
18	SOCKET, COAXIAL	CS-656
18	FERRULE	FR-3
4	CONTACT SOCKET	CS-676
4	CONNECTOR COVER	7152-305
4	FIXED JACKSCREW, FEMALE	CS-661
4	FIXED JACKSCREW, MALE	CS-660
17	TERMINAL, (TEFLON)	TE-111
2	STANDOFF	FA-171-4
8	RELAY SHIELD (LARGE)	7152-307
4	RELAY SHIELD (SMALL)	7152-308

7152-100.DN

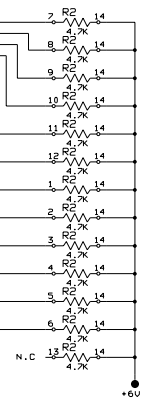
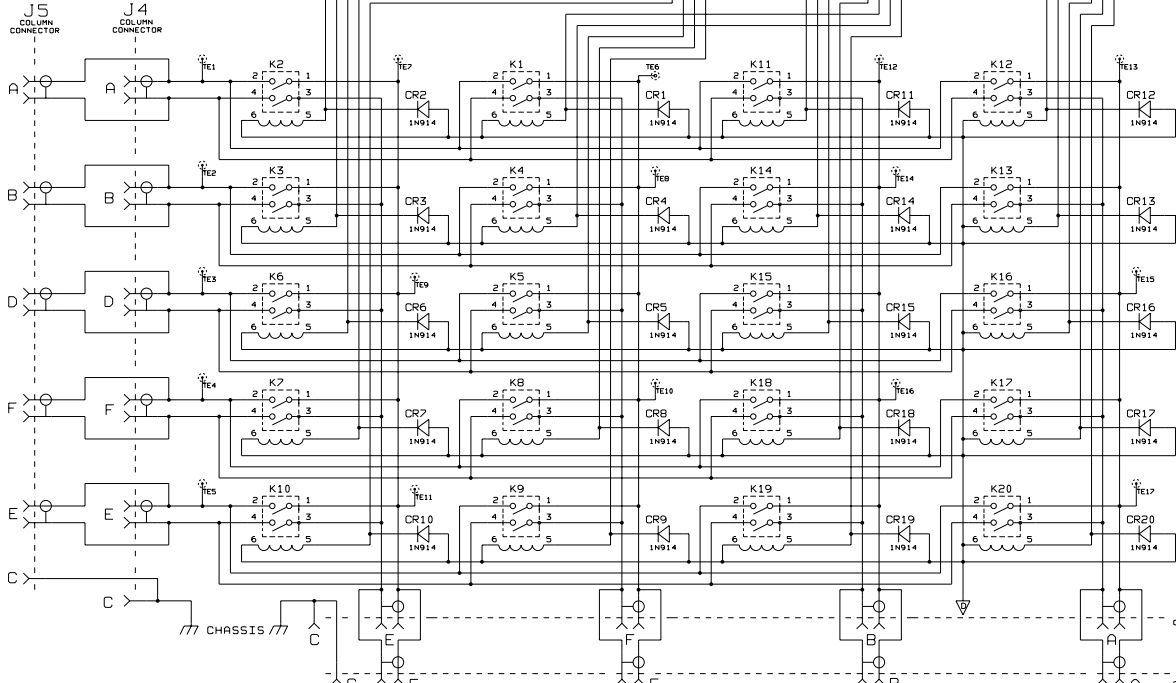
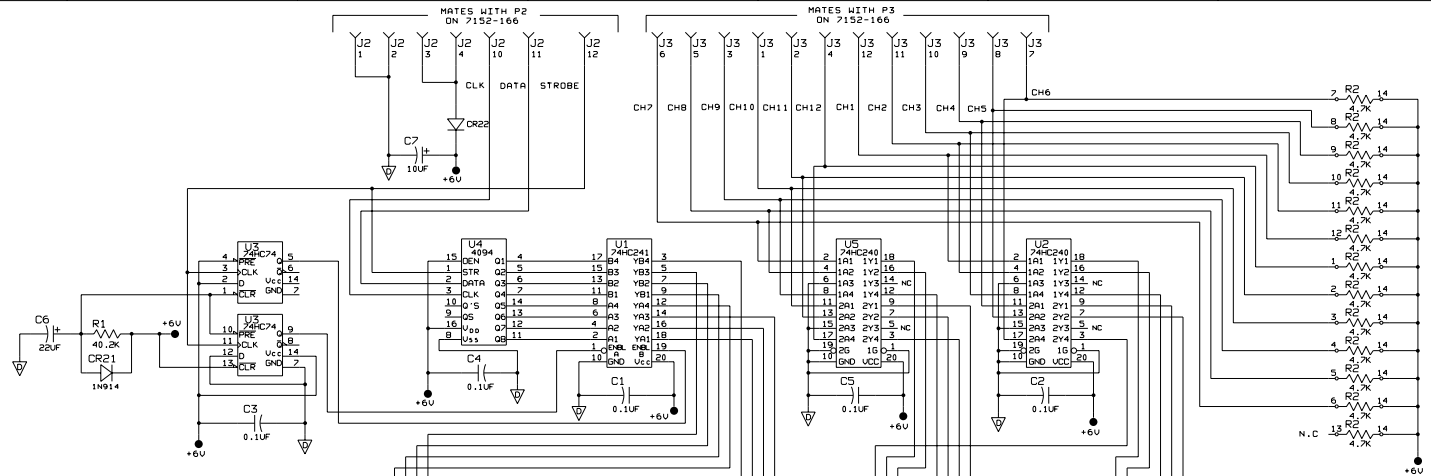
LTR.	ECO NO.	REVISION	ENG.	DATE
C	13027	RELEASED	MJ	9-23-88
D	13240	REVISED	SZ	4-7-89



NOTE: FOR COMPONENT INFORMATION,
SEE BILL OF MATERIAL
7152-000-00.

MODEL	NEXT ASSEMBLY	QTY
7152		

DO NOT SCALE THIS DRAWING	DIMENSIONAL TOLERANCES UNLESS OTHERWISE SPECIFIED	DATE 9/14/88	SCALE 1:1	TITLE COMPONENT LAYOUT, LOW CURRENT MATRIX CARD
KEITHLEY KEITHLEY INSTRUMENTS INC CLEVELAND, OHIO 44139	XX±.015	ANG. ±1°	DRN. MH	ENG. MJ RLC
	XXX±.005	FRAC. ±1/64	MATERIAL	NO. 7152-100
	SURFACE MAX. ϕ	FINISH		C



CONNECTOR	REAR CONTACT	AC CONTACT	DC CONTACT
CHAR1	A	B	1
J6 ROW 2	B	A	2
J7 ROW 3	F	E	4
ROW 4	E	F	5
CHASSIS C	D	G	
COLUMN 1	A	B	1
J6 COLUMN 2	B	A	2
J6 COLUMN 3	D	C	3
COLUMN 4	F	E	4
COLUMN 5	E	F	5
CHASSIS	C	D	6

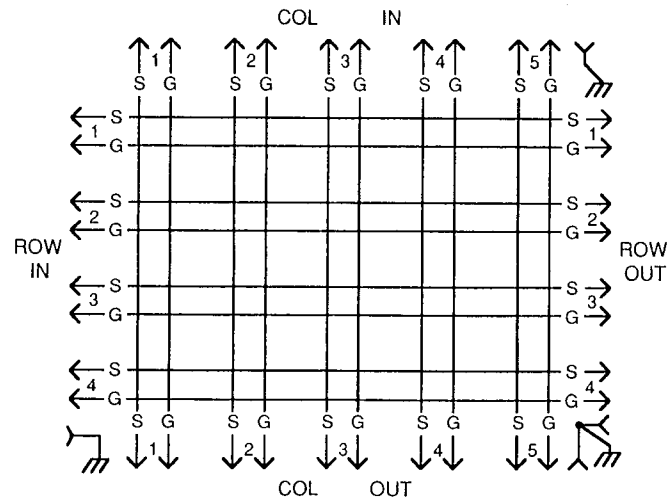
KEITHLEY KEITHLEY INSTRUMENTS INC.
 CLEVELAND, OHIO 44139

SCHEMATIC, LOW CURRENT MATRIX

SIZE: MODEL: D 7152 NO: 7152-106 REV: 13240
 DESIGN: MMH APPROVED: RLC DATE: 3/29/89

APPENDIX A

System Configuration Worksheet



SYSTEM:	_____
MAINFRAME:	_____
SLOT:	_____
DATE:	_____
REVISION:	_____



Service Form

Model No. _____ Serial No. _____ Date _____

Name and Telephone No. _____

Company _____

List all control settings, describe problem and check boxes that apply to problem.

- Intermittent
- IEEE failure
- All ranges or functions are bad
- Particular range or function bad; specify _____

- Front panel operational
- Analog output follows display
- Obvious problem on power-up
- Batteries and fuses are OK
- Checked all cables

Display or output (check one)

- Drifts
- Unstable
- Overload
- Unable to zero
- Will not read applied input

- Calibration only
- Data required
- Certificate of calibration required

(attach any additional sheets as necessary)

Show a block diagram of your measurement system including all instruments connected (whether power is turned on or not). Also, describe signal source.

Where is the measurement being performed? (factory, controlled laboratory, out-of-doors, etc.)

What power line voltage is used? _____ Ambient temperature? _____ °F

Relative humidity? _____ Other? _____

Any additional information. (If special modifications have been made by the user, please describe.) _____

Be sure to include your name and phone number on this service form.

Specifications are subject to change without notice.

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1-888-KEITHLEY (534-8453) www.keithley.com